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(54) **DISPLAY ELEMENT DRIVING APPARATUS
AND DISPLAY USING THE SAME**

(52) **U.S. Cl. 349/151**

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(57) **ABSTRACT**

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A liquid crystal panel includes a plurality of a data line electrode and a plurality of a scanning line electrode crossing each other and forming a pixel arranged in a matrix at the intersection of these two. A mounting package is connected to an edge of a side of a glass substrate of the liquid crystal panel. On an insulating film base of the mounting package, an LSI chip for driving the data line electrode and an LSI chip for driving the scanning line electrode are mounted. The former LSI chip is provided to be close to the liquid crystal panel compared to the latter. A set of wires connecting a group of connecting terminals to the LSI chip is fixed on the film base so as to pass under the LSI chip (mounting area) on the film base. On this account, it is possible to provide a set of wires, which is not connected to the drive LSI chip, in the shortest distance without disconnecting the same, in an arrangement in which a plurality of drive LSI chips is mounted on the liquid crystal panel etc.

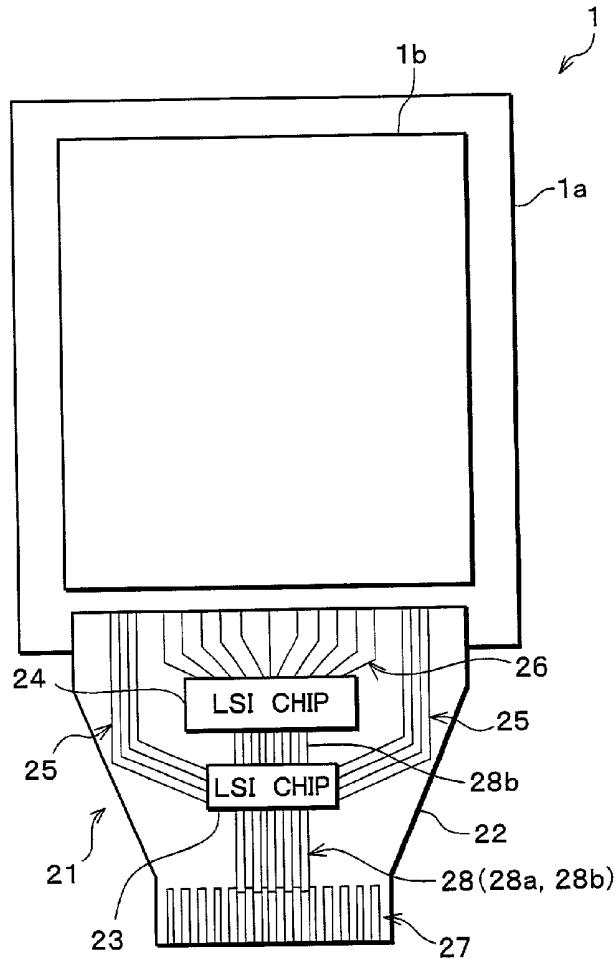
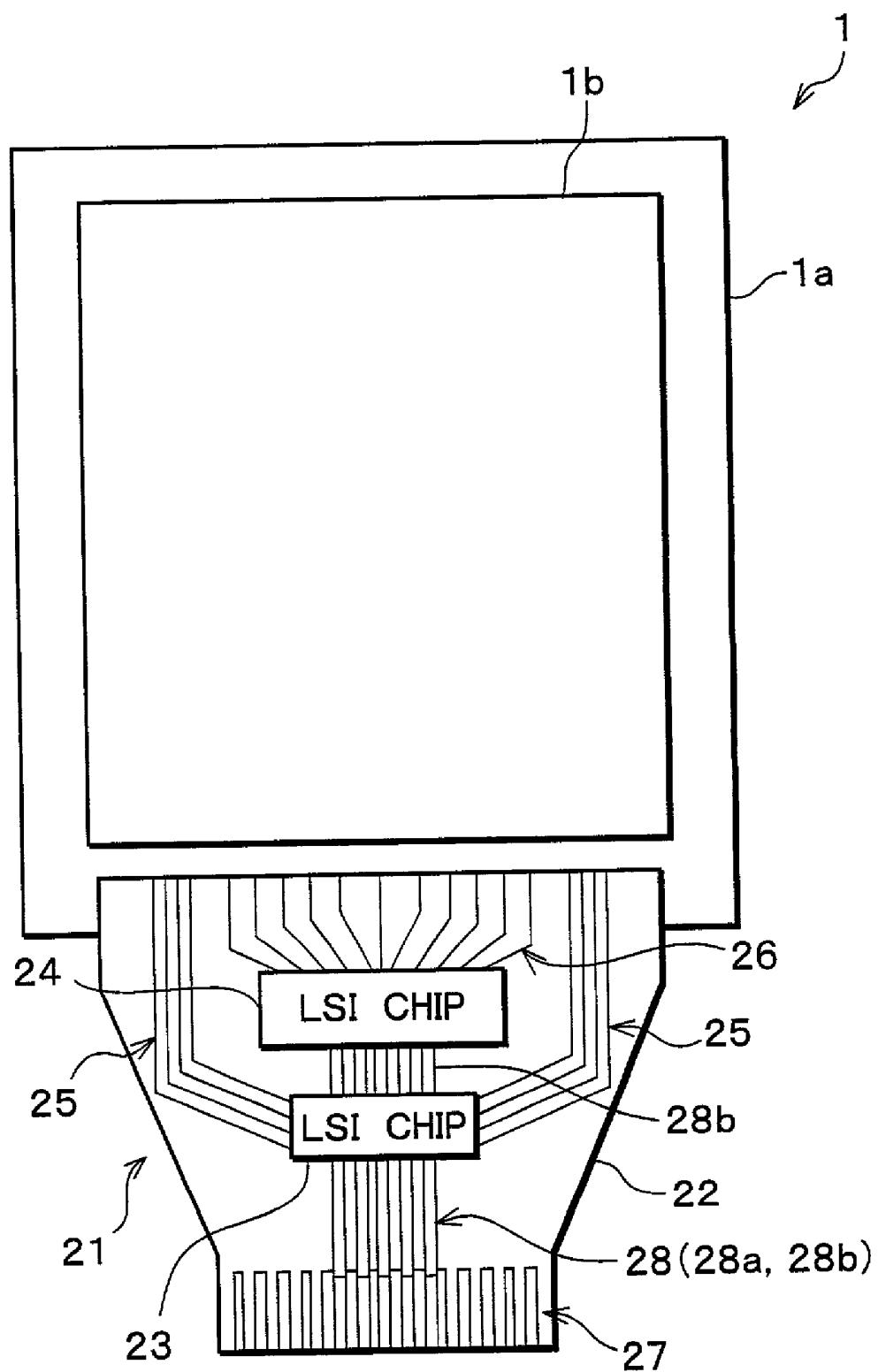


FIG. 1



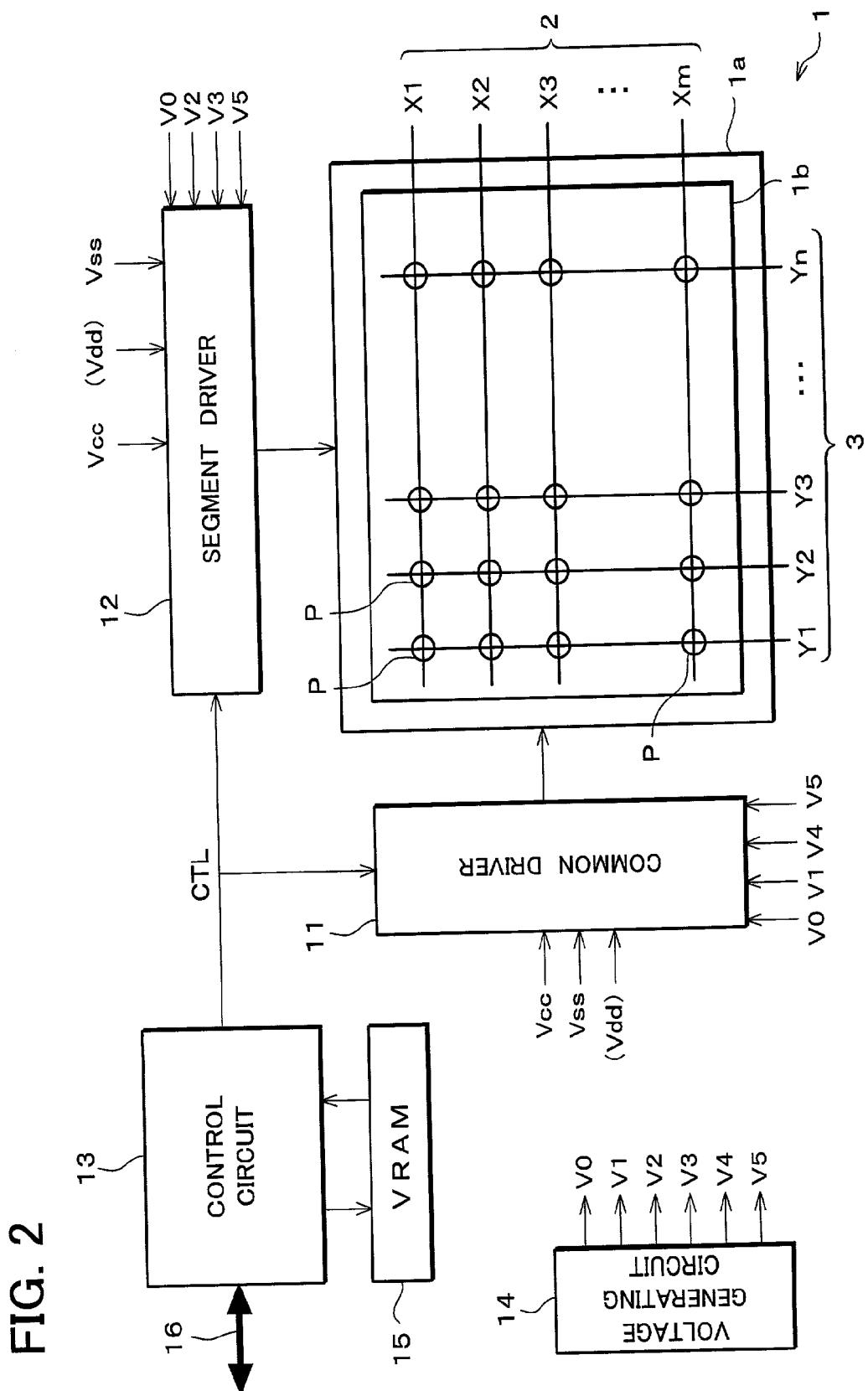


FIG. 3 (a)

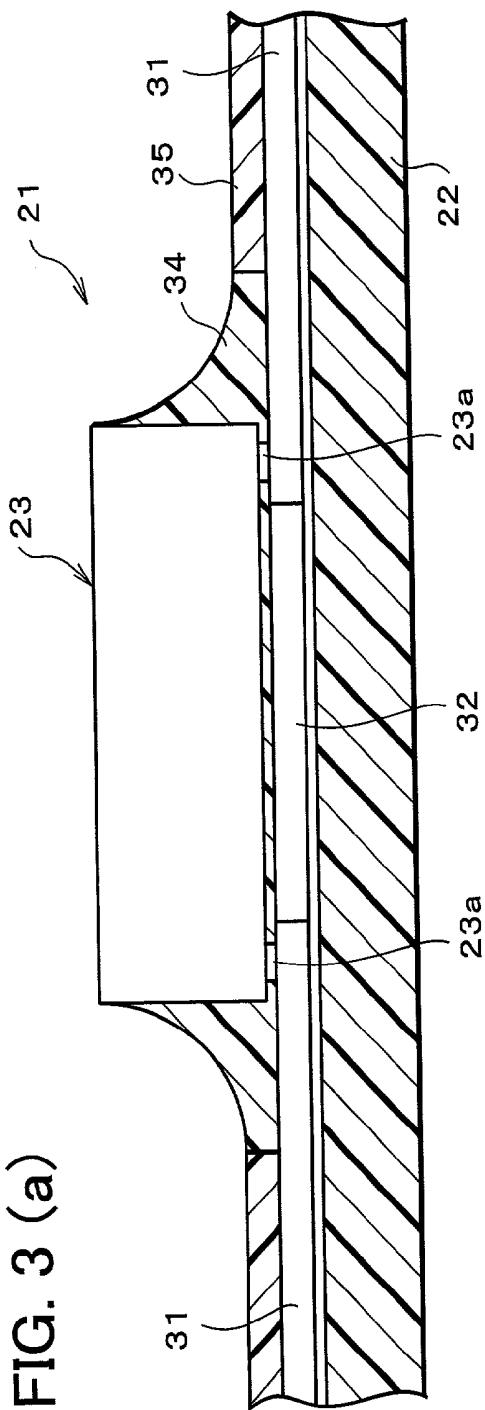


FIG. 3 (b)

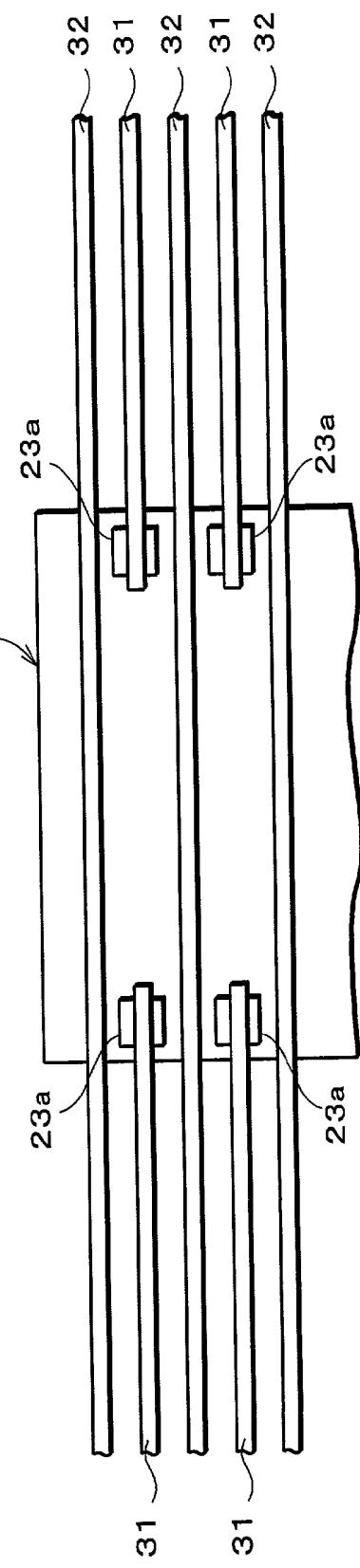


FIG. 4

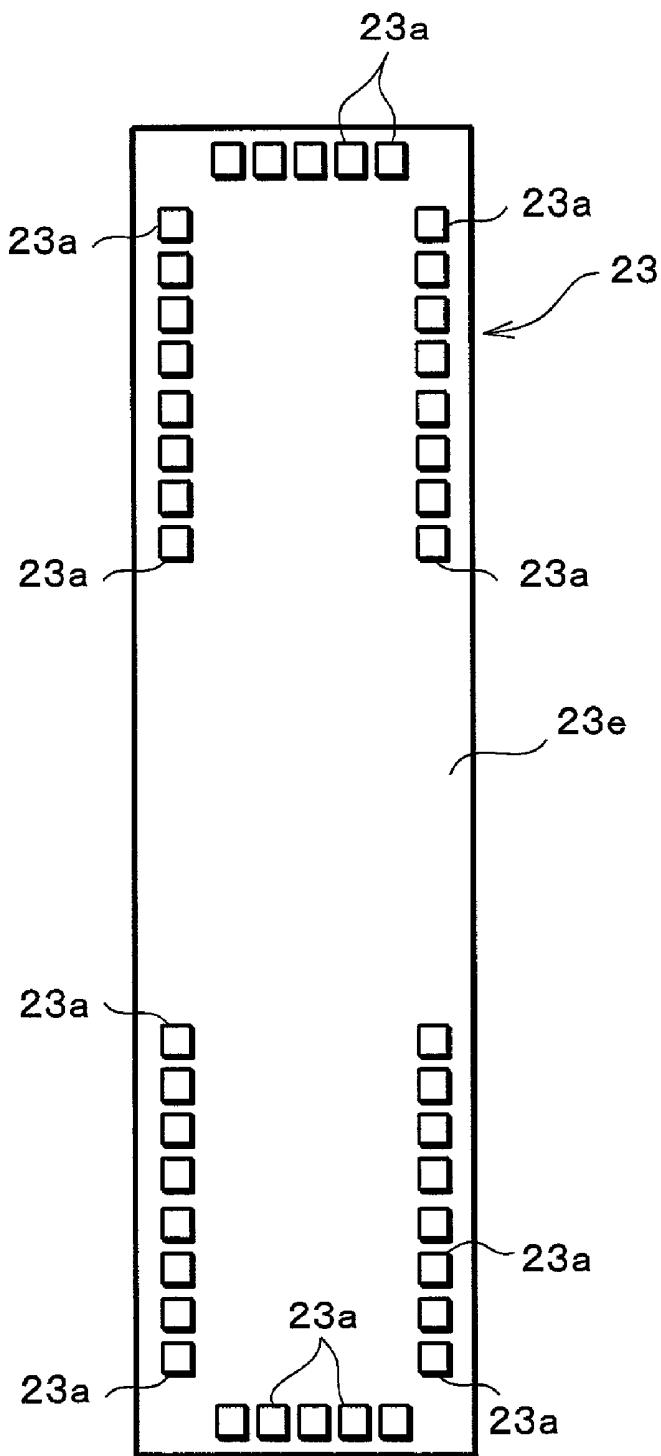


FIG. 5

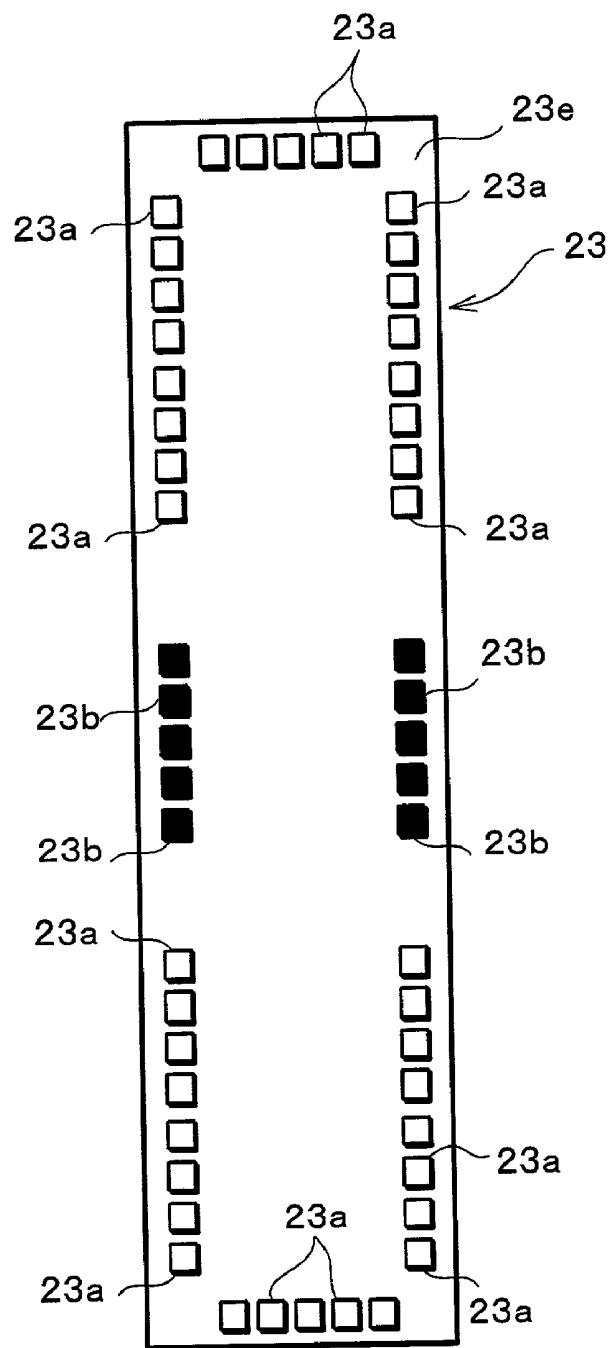


FIG. 6

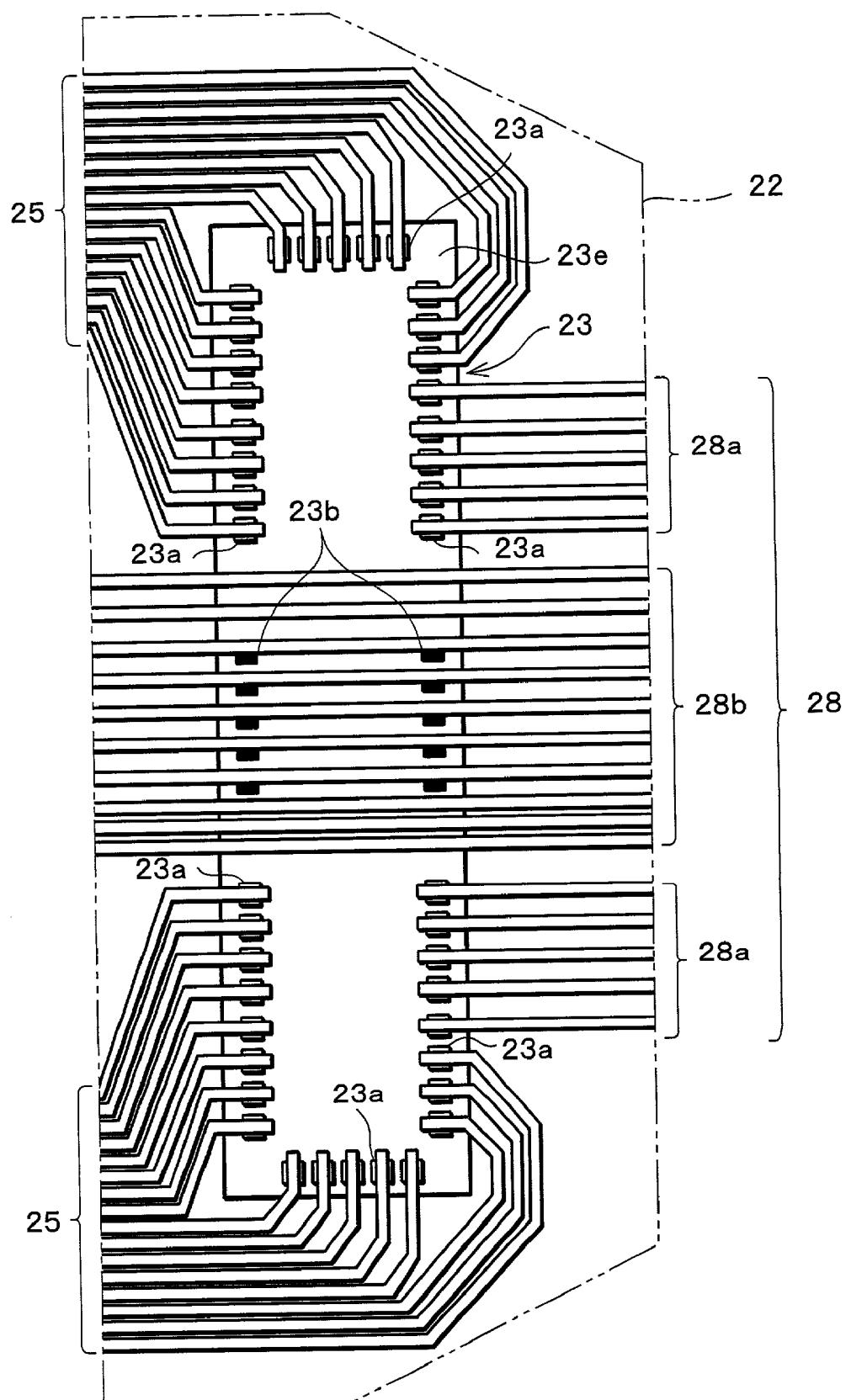


FIG. 7

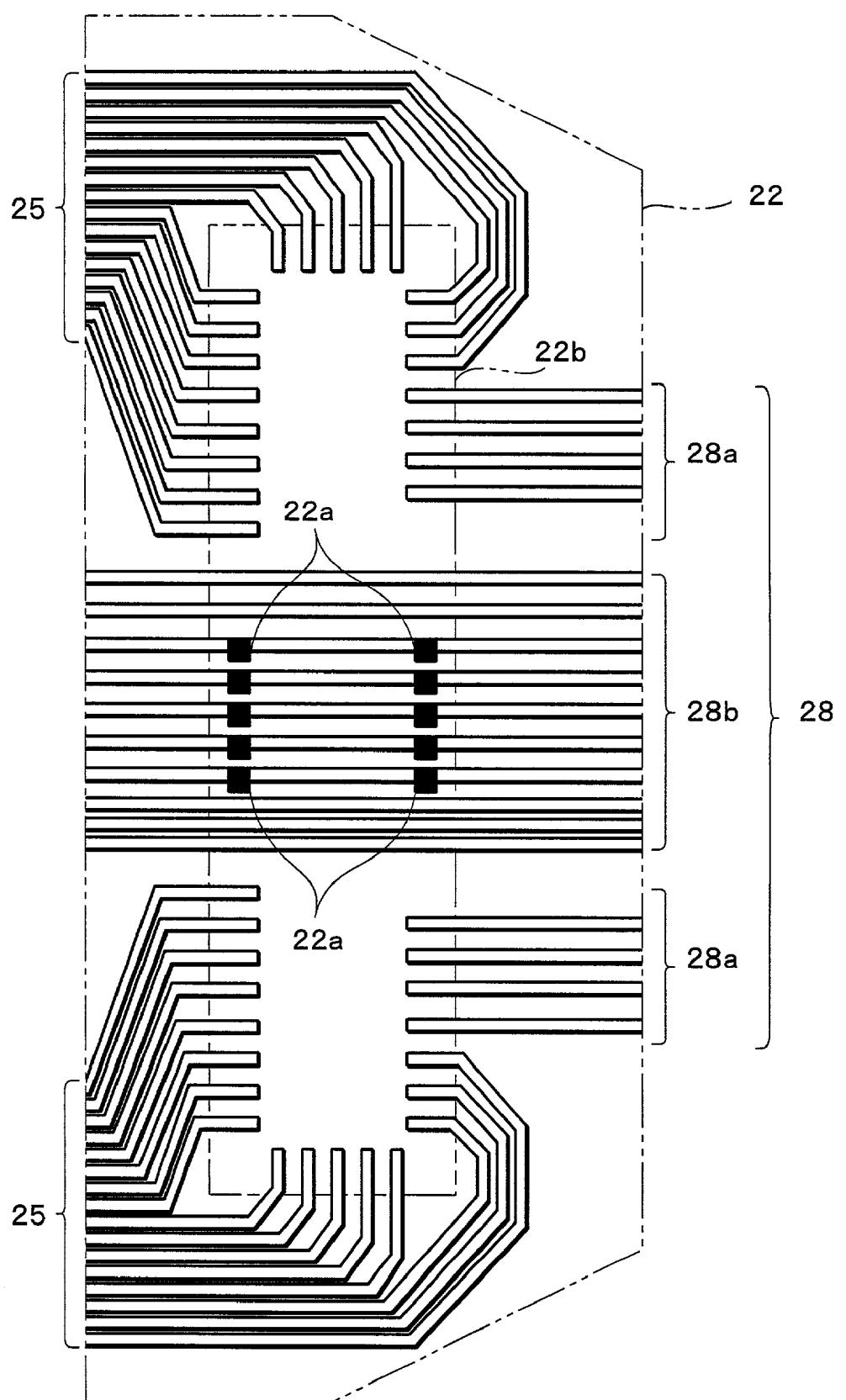


FIG. 8

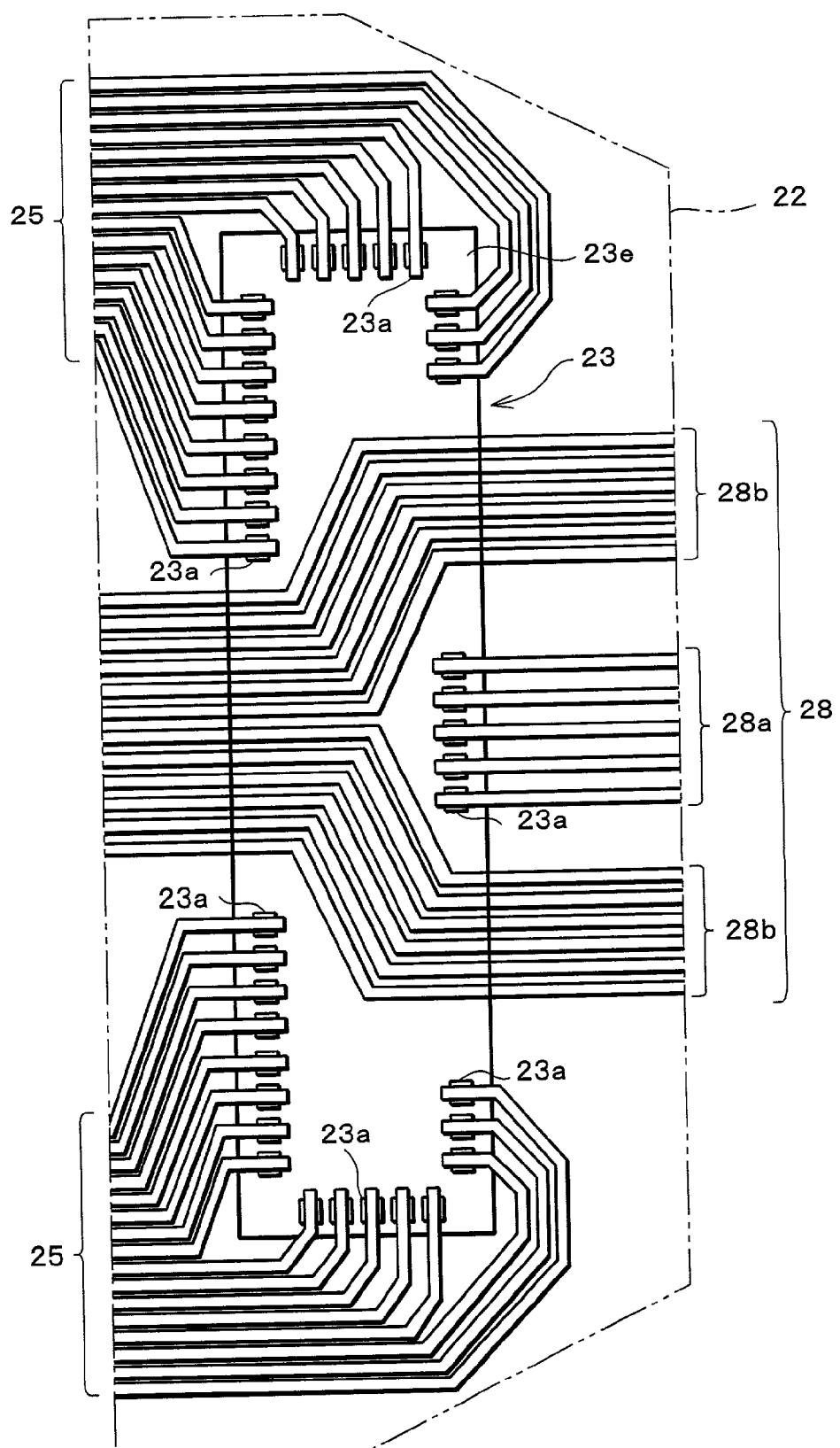


FIG. 9

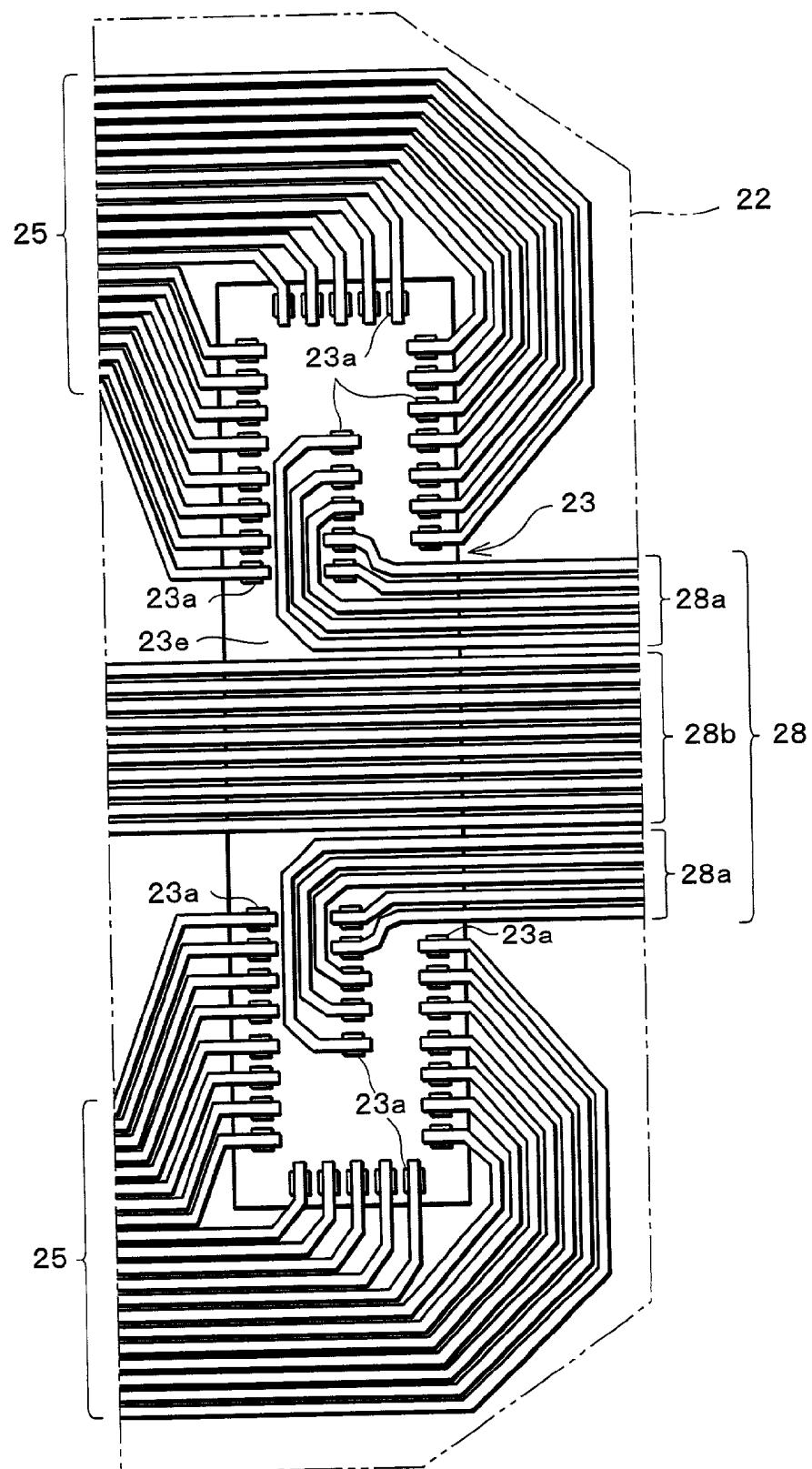


FIG. 10

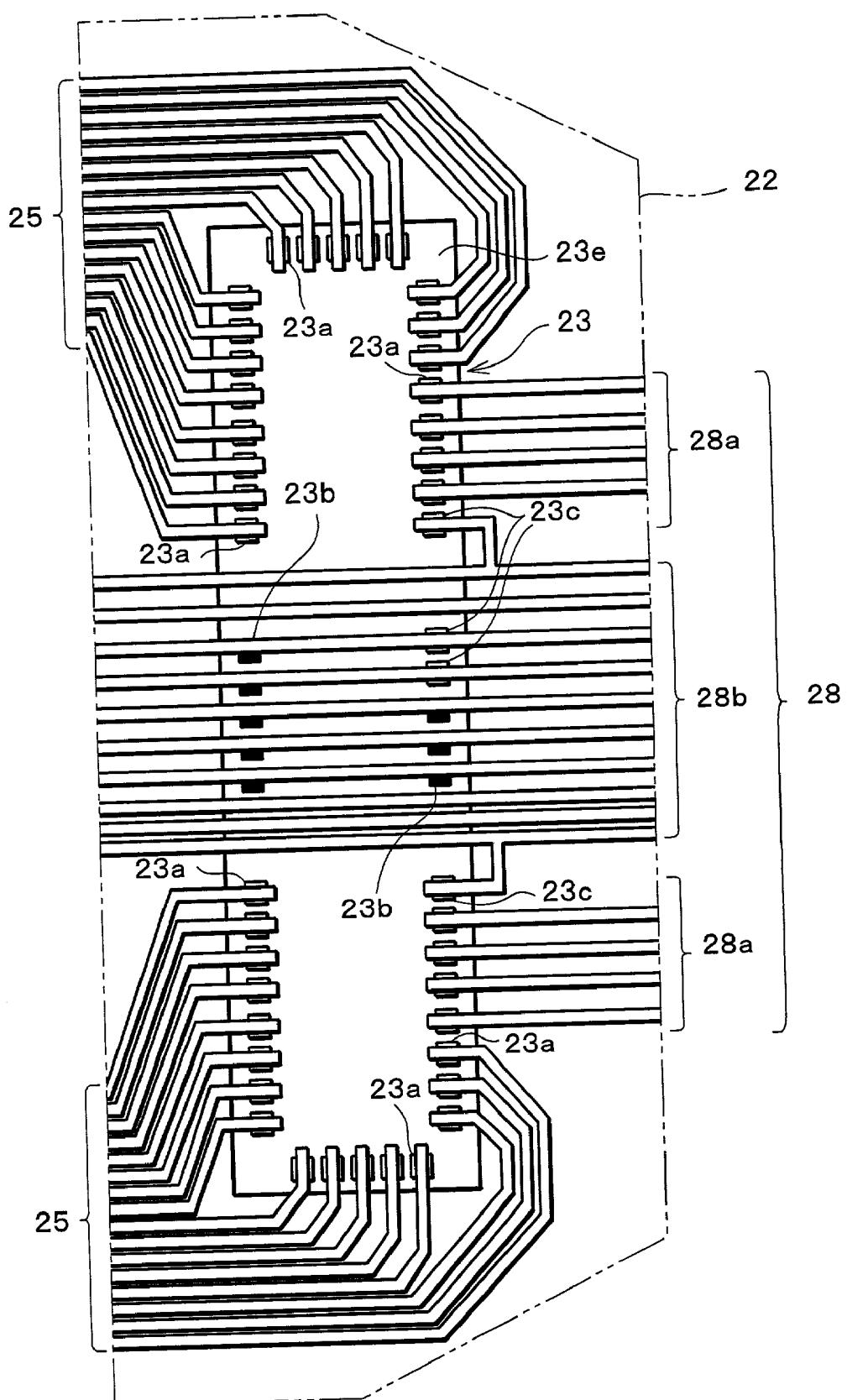


FIG. 11 (a)

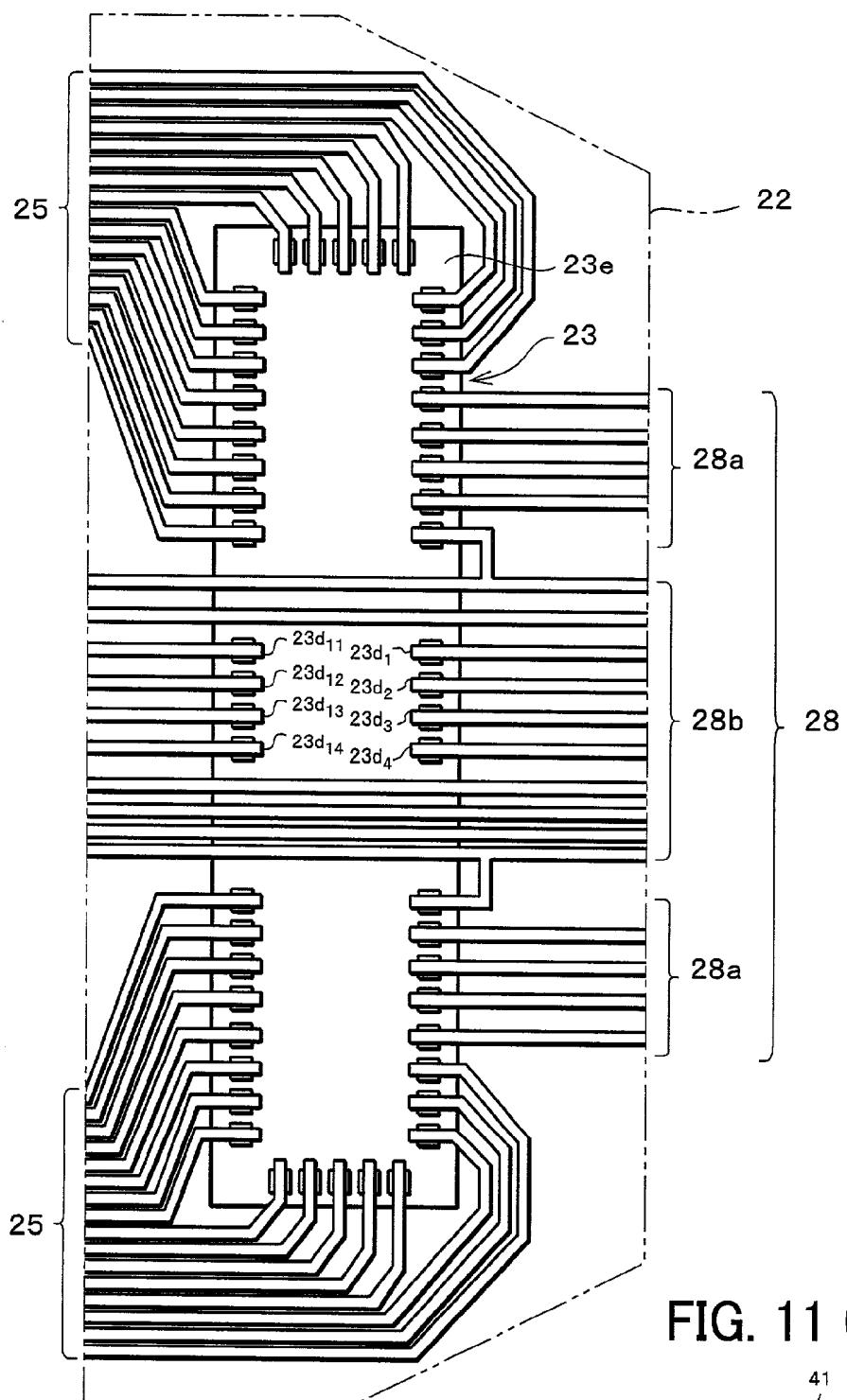


FIG. 11 (b)

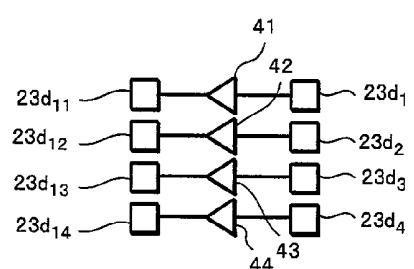


FIG. 12

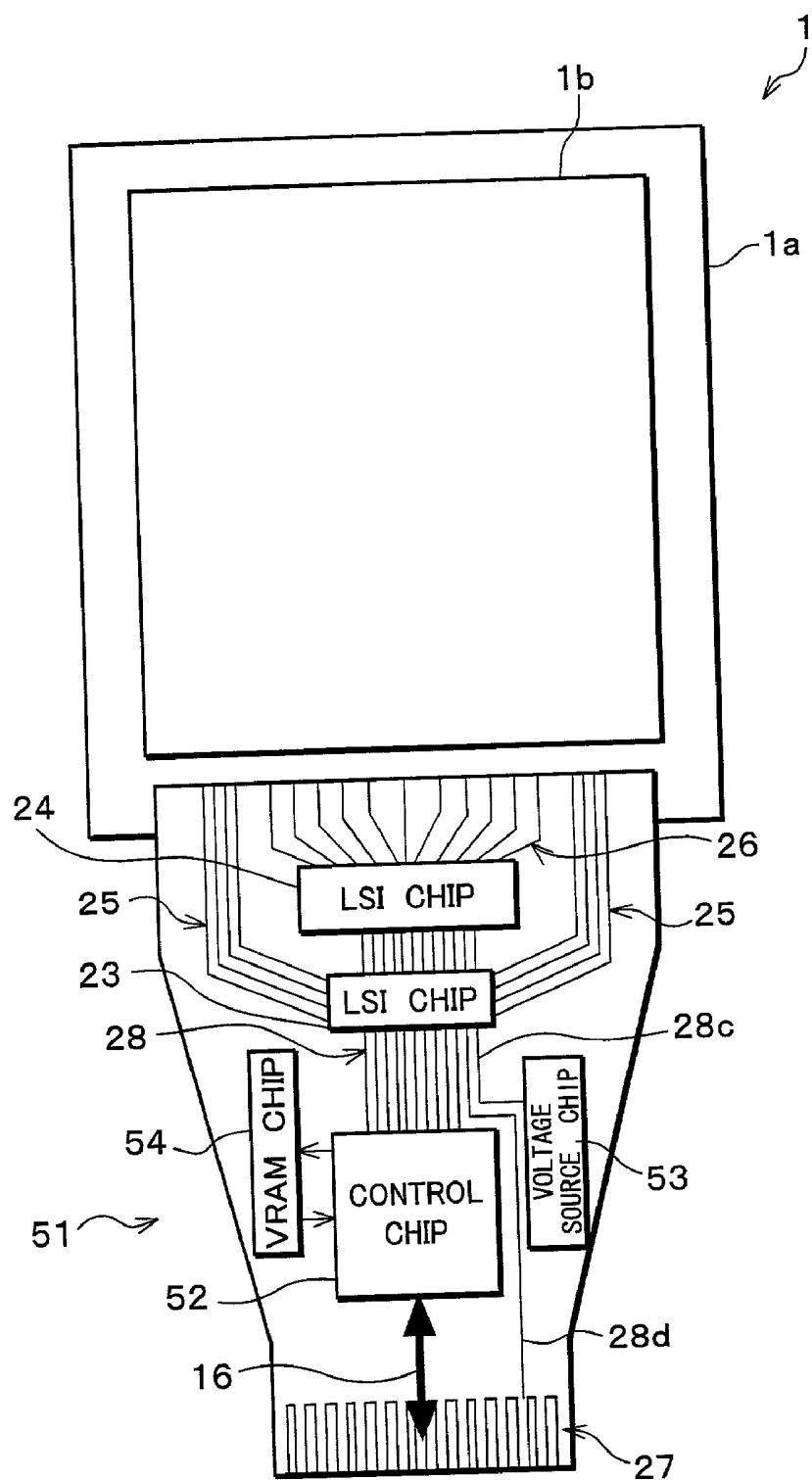


FIG. 13

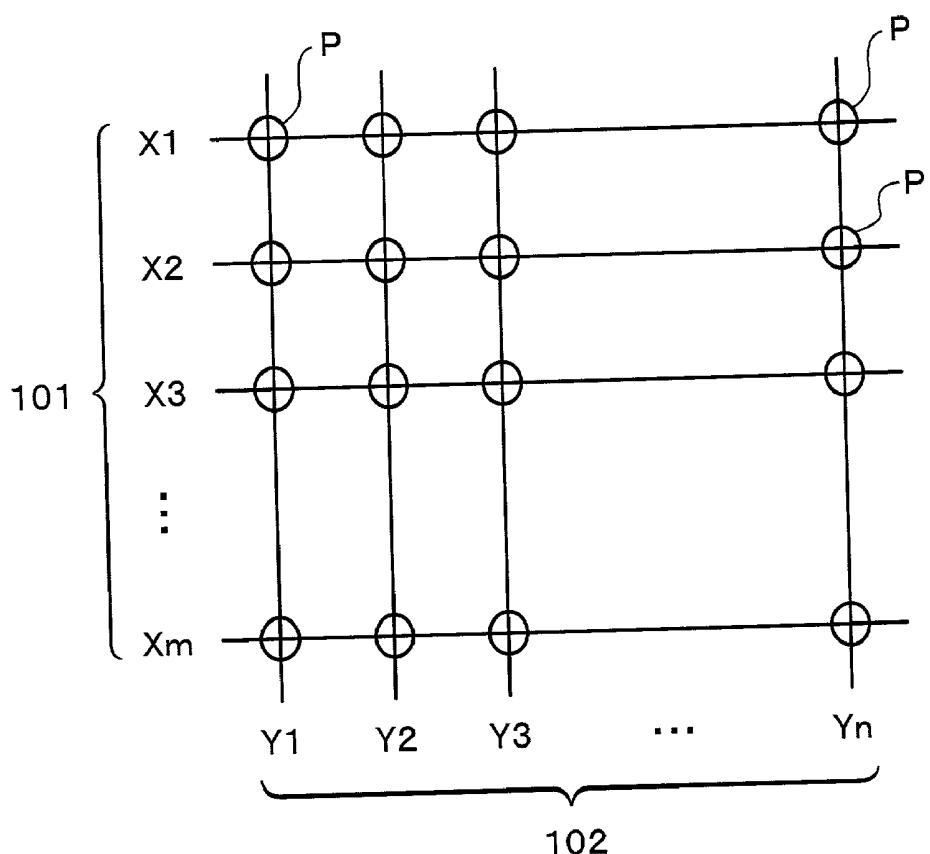


FIG. 14
(PRIOR ART)

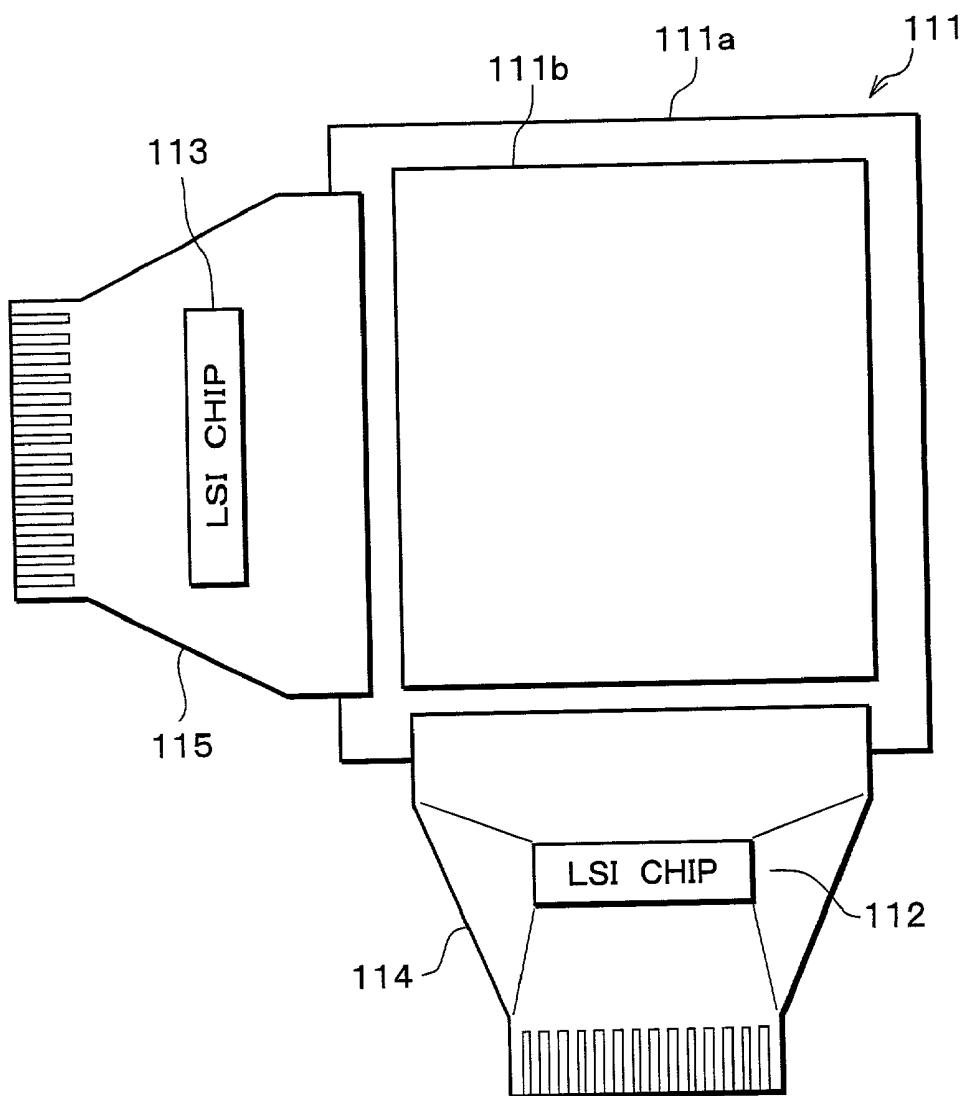


FIG. 15
(PRIOR ART)

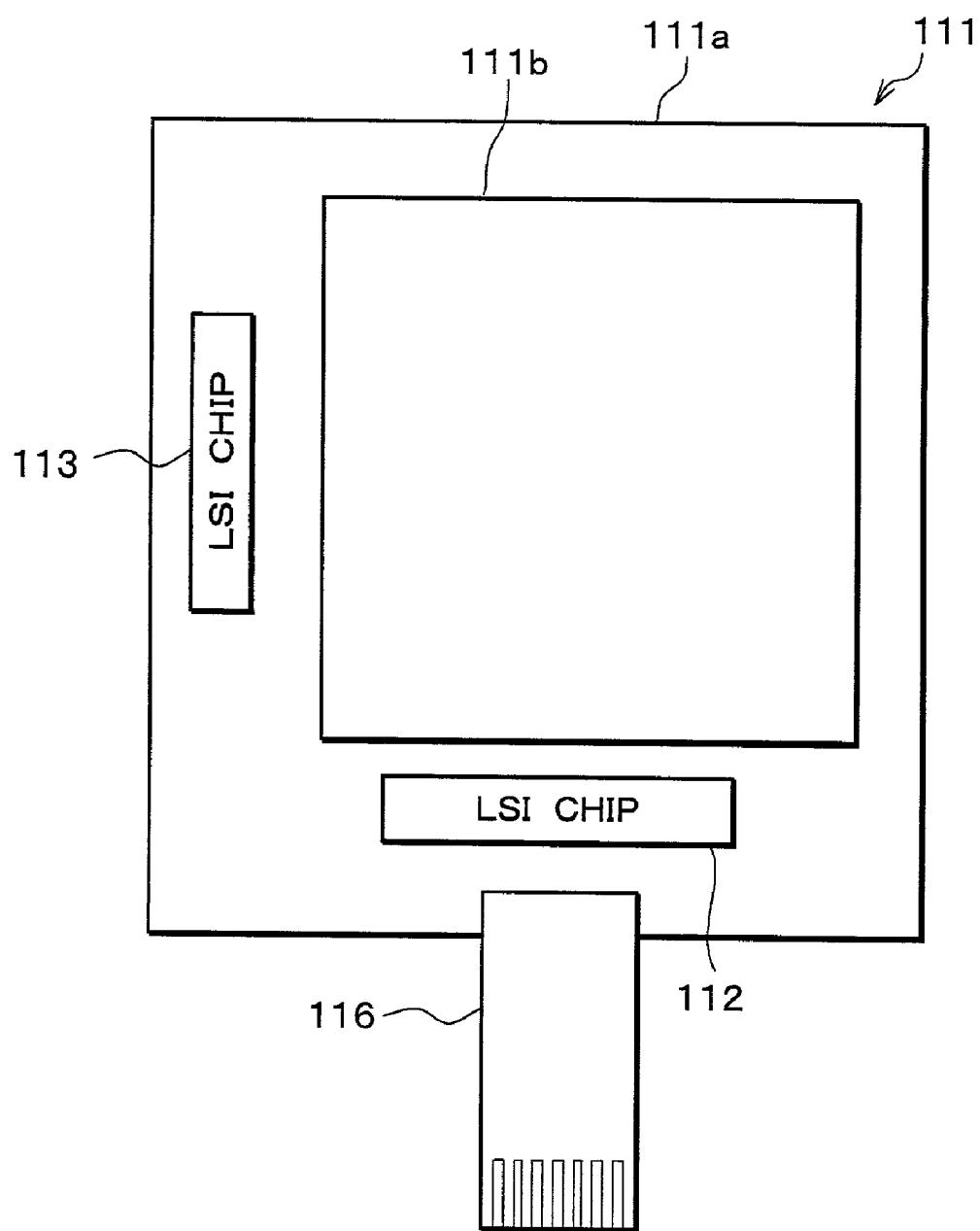


FIG. 16
(PRIOR ART)

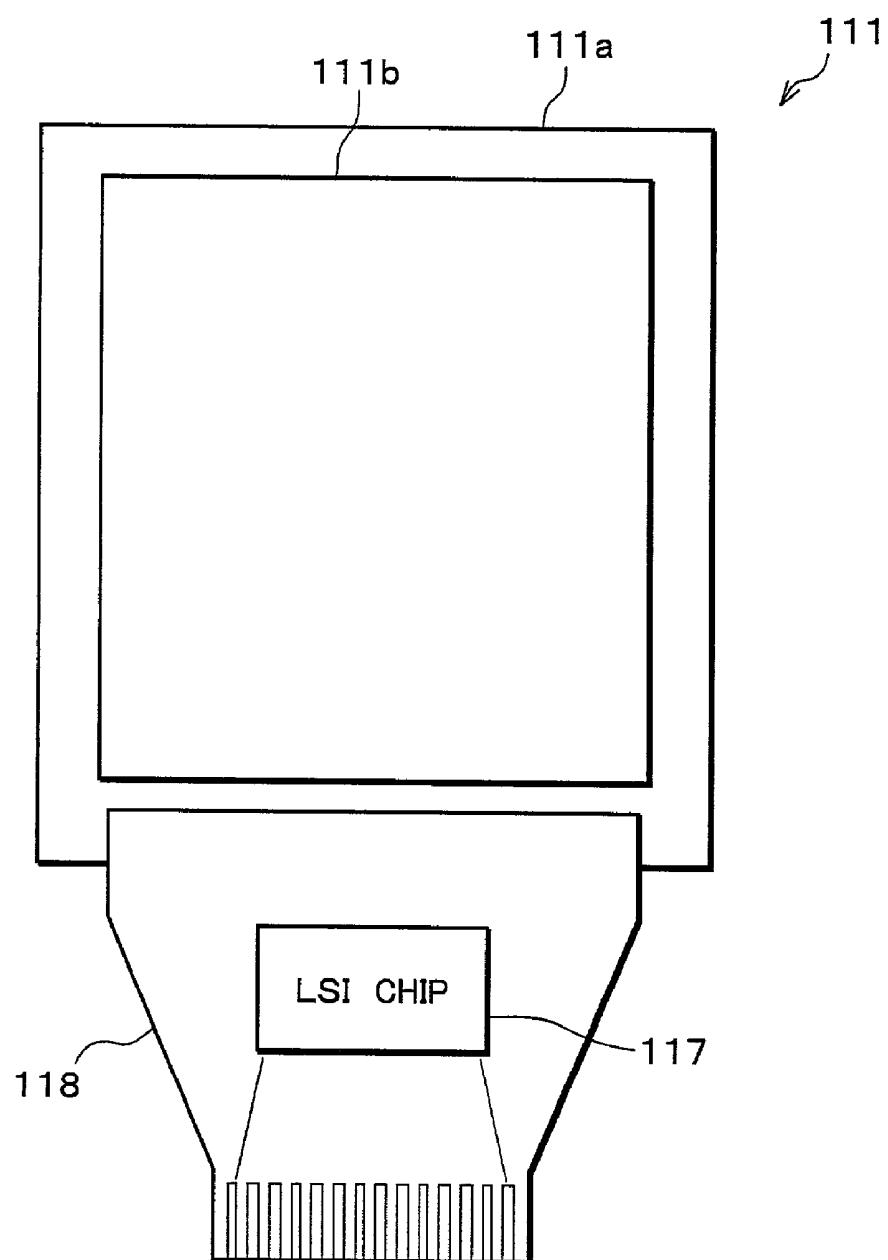


FIG. 17
(PRIOR ART)

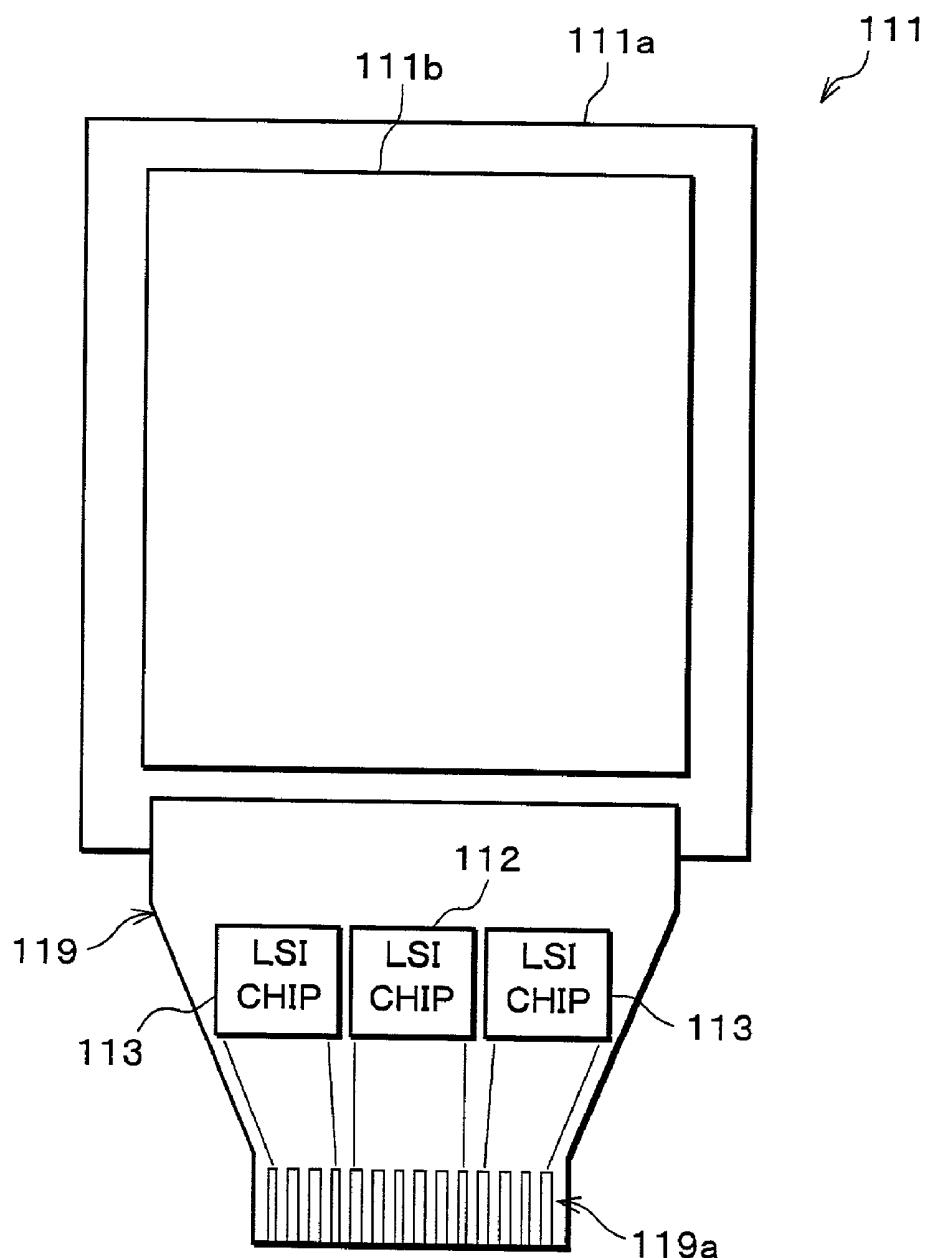


FIG. 18
(PRIOR ART)

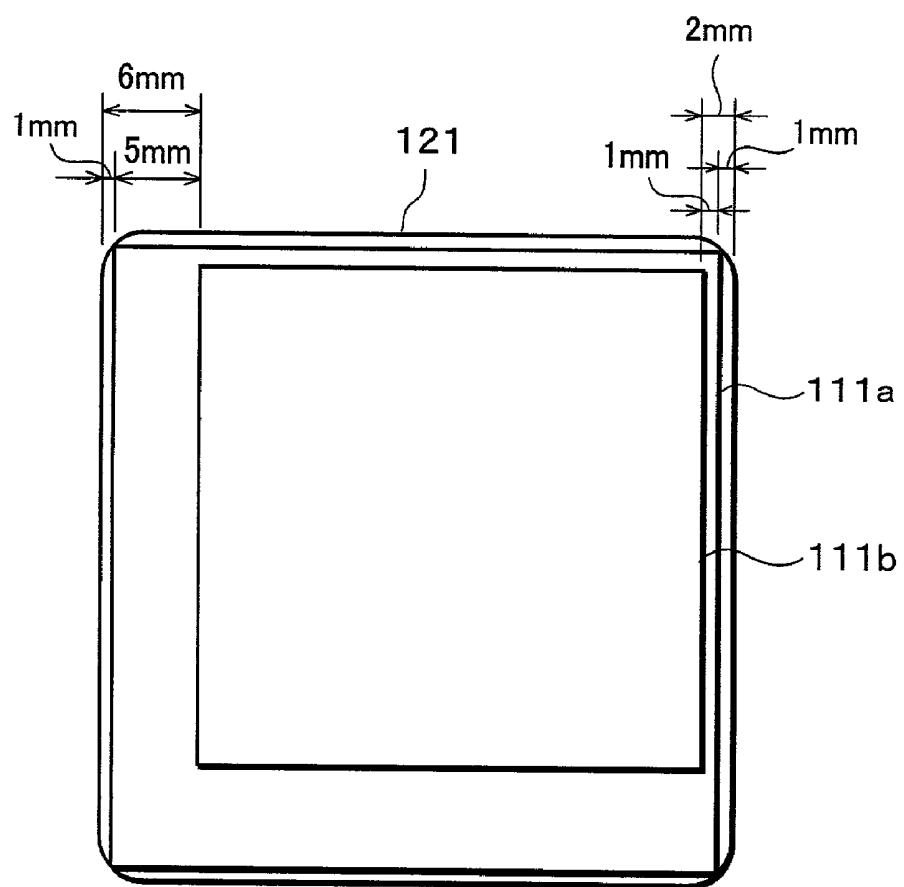


FIG. 19
(PRIOR ART)

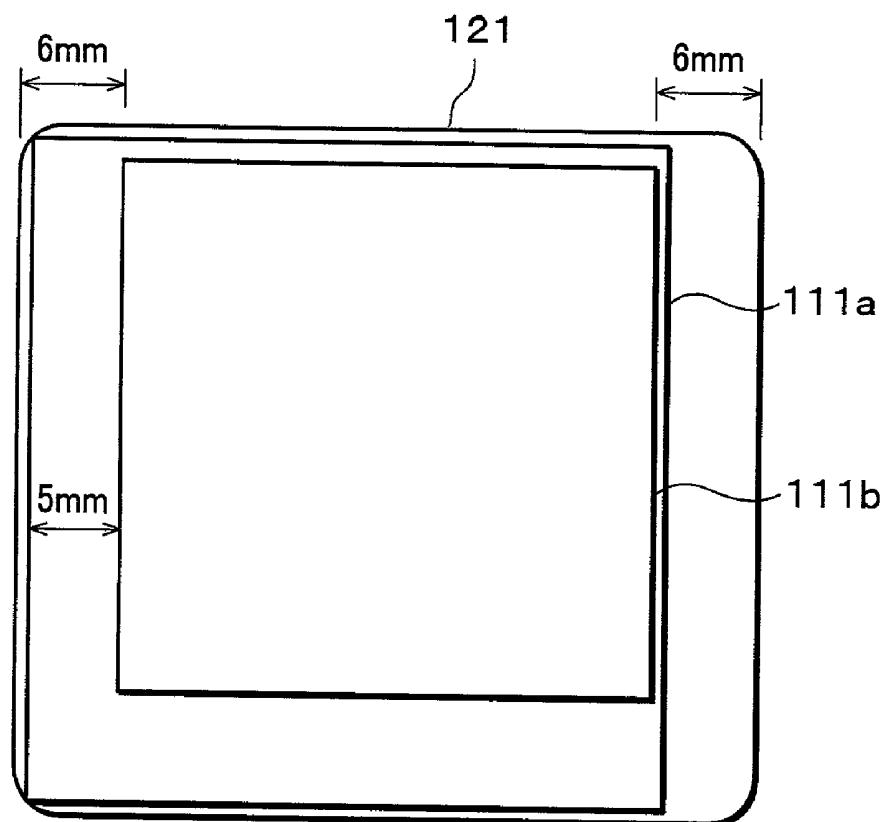
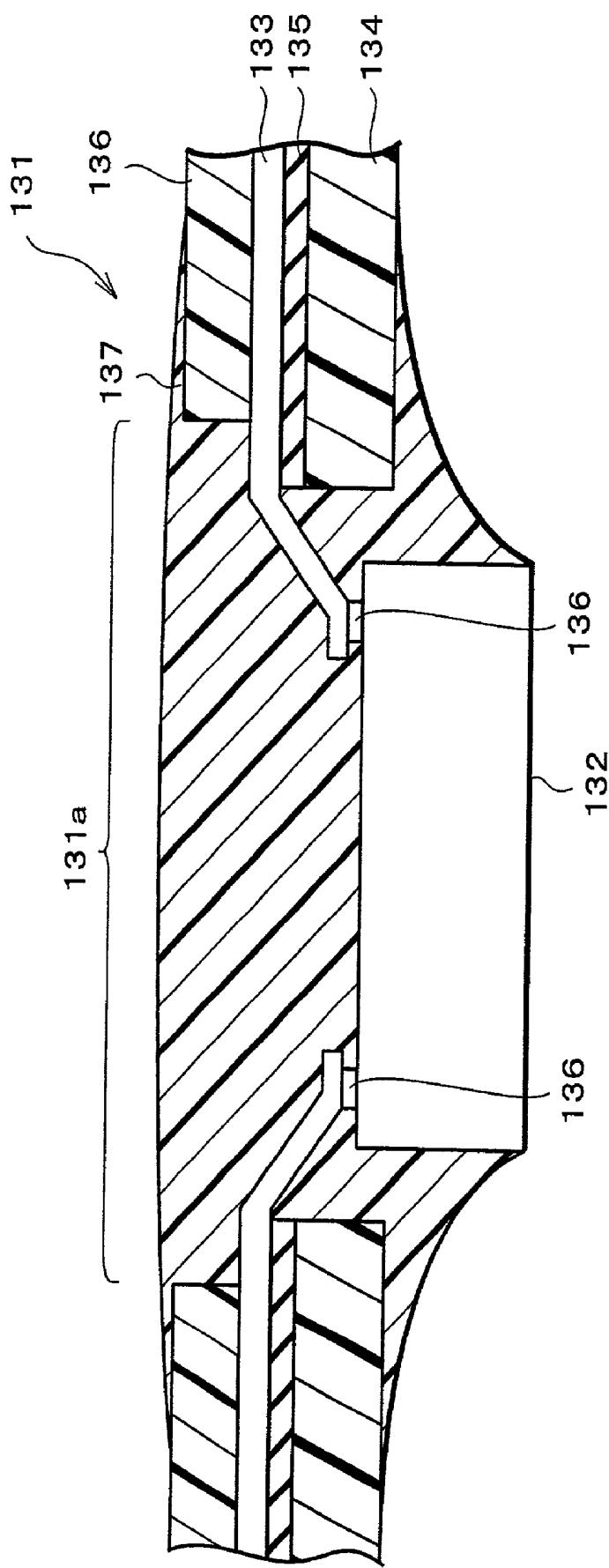


FIG. 20
(PRIOR ART)



DISPLAY ELEMENT DRIVING APPARATUS AND DISPLAY USING THE SAME

FIELD OF THE INVENTION

[0001] The present invention relates to a display element driving apparatus including an integrated circuit mounted on a mounting substrate connected to the display element, into which drive circuits for driving a display element such as a liquid crystal display element are integrated, and a display including the same.

BACKGROUND OF THE INVENTION

[0002] A matrix-type liquid crystal display panel conventionally has a structure shown in **FIG. 13**. To be more specific, this liquid crystal display panel includes a group **101** of scanning line electrodes, a group **102** of data line electrodes, and a liquid crystal (not illustrated) sandwiched between the groups **101** and **102**. The group **101** of scanning line electrodes is made up of scanning line electrodes X_1 to X_m provided sideways and being in parallel with each other. Meanwhile, the group **102** of data line electrodes is made up of data line electrodes Y_1 to Y_n provided longitudinally and being in parallel with each other, and also crossing the scanning line electrodes X_1 to X_m at right angles. Moreover, a pixel P is formed at the intersection of a scanning electrode X_i ($m=i$) and a data line electrode Y_j ($n=j$).

[0003] For instance, typical driving method of this kind of liquid crystal display panel is explained in publications including Japanese Laid-Open Patent Application No. 60-222835/1985 (Tokukaisho 60-222835; published on Nov. 7, 1985) titled "Driving Method of Liquid Crystal Matrix Display Panel" and Japanese Laid-Open Patent Application No. 62-3229/1987 (Tokukaisho 62-3229; published on Jan. 9, 1987) titled "Liquid Crystal Driving Method". These driving methods apply a voltage sufficient to alter an optical characteristic (transparency) of liquid crystal of the pixel by transmitting a signal to the pixel via the scanning line electrode and data line electrode, when the liquid crystal of the pixel is addressed. Matrix-type liquid crystal displays applying a voltage to a pixel have this kind of addressing method in common, regardless of the types of the panels such as TFT (Thin Film Transistor) and STN (Super Twisted Nematic).

[0004] As the driving methods above show, transmitting the scanning signal and the data signal to the pixel is necessary for driving the matrix-type liquid crystal display panel. Thus as **FIGS. 14 and 15** show, the liquid crystal display panel **111** is conventionally arranged so that an LSI chip **112** for driving data lines (hereinafter, will be simply referred to as data LSI chip) is provided on a side of a display area **111b** formed on a glass substrate **111a** of a liquid crystal panel **111**, whereas an LSI chip **113** for driving scanning lines (hereinafter, will be simply referred to as scanning LSI chip) is provided on another side of the liquid crystal panel **111**.

[0005] In the arrangement shown in **FIG. 14**, a TCP (Tape Carrier Package) **114** on which the data LSI chip **112** ("LSI Chip" in the figure) is mounted and a TCP **115** on which the scanning LSI chip **113** ("LSI Chip" in the figure) is mounted are connected to the glass substrate **111a** on which electrodes are provided.

[0006] In the arrangement shown in **FIG. 15**, the LSI chips **112** and **113** are directly mounted on the glass substrate **111a** by a method termed COG (Chip On Glass). Moreover, a flexible printed board **116**, for transmitting a control signal and applying a supply voltage to the LSI chips **112** and **113**, is connected to the glass substrate **111a**.

[0007] There is another arrangement such that, as shown in **FIG. 16**, a TCP **118** on which a single LSI chip **117** ("LSI Chip" in the figure) is mounted is connected to a side of the glass substrate **111a** (see Japanese Laid-Open Patent Application No. 6-34987/1994 (Tokukaihei 6-34987; published on Feb. 10, 1994)). In the LSI chip **117**, driving circuits generating the data signal and the scanning signal are integrated altogether.

[0008] There is a further arrangement such that, as **FIG. 17** shows, two scanning LSI chips **113** are provided on opposing sides of the data LSI chip **112** and on the TCP **119**, and the TCP **119** is connected to a side of the glass substrate **111a** (see Japanese Laid-Open Patent Application No. 6-34987/1994 (Tokukaihei 6-34987; published on Feb. 10, 1994) and Japanese Laid-Open Patent Application No. 6-11721/1994 (Tokukaihei 6-11721; published on Jan. 21, 1994)). In this arrangement the display area **111b** is provided on the center of the glass substrate **111a** so that sets of wires for the scanning electrodes, which extend from the TCP **119** to the display area **111b**, are separately provided on both sides of the display area **111b**. On this account, two scanning LSI chips **113** are provided.

[0009] However, the conventional arrangements shown in **FIGS. 14 and 15** require to provide two LSI chips **112** and **113** for generating a driving signal on at least two sides of the liquid crystal panel **111**. Thus as **FIG. 14** shows, at least TCPs **114** and **115** on which the chips above are mounted are required so that the arrangements should be complicated and demand greater numbers of the parts accordingly. Therefore this type of arrangement costs a lot.

[0010] When the COG technique shown in **FIG. 15** is employed, it is required that the data LSI chip **112** and the scanning LSI chip **113** are mounted on at least two sides of the glass substrate **111a**. In this arrangement the center of the glass substrate **111a** and that of the display area **111b** are not matched when actually mounted so that a non-display area (frame) surrounding the display area **111b** has to be broad, to match the center of a device, on which the liquid crystal panel **111** is mounted, with the center of the display area **111b**.

[0011] For instance, as **FIG. 18** shows, a non-mounting part of the non-display area of the glass substrate **111a**, on which the LSI chips **112** and **113** are not mounted, is not necessarily broad, whereas a mounting part of the non-display area, on which the LSI chips **112** and **113** are mounted, has to be broad. More specifically, when the width of the mounting part is 5 mm while that of the non-mounting part is 1 mm and the distance between the edge of the glass substrate **111a** and a housing **121** storing the liquid crystal panel **111** is 1 mm, the distance between the edge of the display area **111b** and an interior wall of the housing **121** is 6 mm on the mounting part side, whereas the distance above is 2 mm on the non-mounting part side.

[0012] When the arrangement shown in **FIG. 15** is manufactured in accordance with the dimensions given above, a

device on which the liquid crystal panel 111 is mounted includes, as **FIG. 18** shows, the display area 111b provided on the right-hand side of the housing 121. Although it depends on the shape of a device, generally the device looks good when the center of the display area 111a is at an equal distance from both right and left edges of the housing 121. (Directions such as above, below, right, and left mentioned in this description are defined as those for a viewer of the display.) On this account, to form the housing 121 symmetrically, it is required to set both of distances between the right edge of the display area 111b and the interior wall of the housing 121 and between the left edge thereof and the interior wall thereof to 6 mm. However, the sideward length of this housing 121 is unnecessarily long.

[0013] The problem of the aforementioned COG arrangement does not much matter for a conventional device using the TCP, since the film can be bent by providing a slit thereon. However, even in the arrangement shown in **FIG. 14**, an area having around 2 mm width is required to connect the TCPs 114 and 115 to the glass substrate 111a so that a similar inconvenience occurs when forming the housing 121, even though the inconvenience is less prominent than the case of the COG.

[0014] The arrangement shown in **FIG. 16** requires to include all circuits for driving the liquid crystal panel 111 in the LSI chip 117. For instance, when a color liquid crystal panel including 128×164 pixels is driven, 128×3 (R, G, B) data line electrodes and 164 scanning line electrodes are required so that the LSI chip 117 has to have 548 driving terminals in total.

[0015] There can be another arrangement so that the data line electrodes are separately provided above and below the display area 111b and hence the liquid crystal panel 111 is driven by two LSI chips respectively provided on the upper and lower sides of the glass substrate 111a. In this arrangement, each of the upper and lower LSI chips has 128×3 data line electrodes and 82 scanning line electrodes and hence each of the two LSI chips has to have 466 driving terminals in total.

[0016] However, cost of an LSI chip including a lot of driving circuits and corresponding terminals is expensive, since the chip is large in size so that only a small number of the chips can be manufactured from one wafer.

[0017] Moreover, generally a voltage sufficient to alter an optical characteristic (transparency) of a liquid crystal material is around 10V as an effective voltage. However, a voltage applied to a liquid crystal is normally converted to alternate current to keep reliability of the liquid crystal material. On this account, around a +10V (or 20V in amplitude) driving voltage may be required in reality, depending on a driving method.

[0018] Compared with a conventional LSI manufacturing process for manufacturing a low-voltage-driven circuit (around 5V) such as a logic circuit, a manufacturing process to manufacture a high-voltage-driven circuit (such as 20V) requires high cost and also the LSI chip thereof has to be large in area to endure a high voltage.

[0019] Some driving methods etc. allow to set a voltage applied to a chip for numerous data line electrodes low. In this case the LSI chip for the data line electrodes can be manufactured in a conventional process for manufacturing a

logic circuit etc. When this kind of LSI chip is employed for the data line electrodes, a voltage driving liquid crystal is insufficient since a driving voltage of a circuit manufactured in the conventional LSI manufacturing process is roughly between 0V and 5V. Thus the liquid crystal driving voltage has to be supplemented by increasing a driving voltage applied to scanning electrodes. On this account, only the LSI chip for the scanning electrodes is manufactured in the process to manufacture the expensive LSI capable of enduring a high voltage, so that it is possible to reduce a total cost for the driving device.

[0020] However, as **FIG. 16** shows, the arrangement employing a single LSI chip 117 cannot divide the LSI chip into the chip for the data line electrodes and that for the scanning line electrodes. On this account, the LSI chip 117 has to be manufactured in the process to manufacture the expensive LSI capable of enduring a high voltage, so that it is not possible to reduce the cost of the LSI chip 117.

[0021] In the meantime, in the arrangement shown in **FIG. 17** two scanning LSI chips 113 are provided on the TCP 119 and hence the data LSI chip 112 and two scanning LSI chips 113 can be manufactured in each different LSI manufacturing process. Thus costs for the LSI chip can be reduced in this arrangement, compared to the arrangement shown in **FIG. 16**. However, including two scanning LSI chips 113 makes it necessary to transmit the control signal for driving scanning lines, which is input from the outside, from both groups of terminals respectively provided on both sides of the connecting terminals 119a of the TCP 119. Thus an arrangement of a surrounding part of the TCP 119 has to be complex and the number of required parts as a driving device is increased, so that the cost is expensive.

[0022] As **FIG. 20** shows, an arrangement below is employed when a drive LSI chip 132 for driving is mounted on a TCP 131. This TCP 131 includes leads 133 for transmitting signals fixed on an insulating film base 134 via an adhesive layer 135. The LSI chip 132 is attached to the leads 133 by fixing bumps 136, provided on a mounting surface of the LSI chip 132, to the leads 133. The leads 133 forming a wiring layer is protected with a protector 136 made up of a solder resist etc. Also the LSI chip 132 and the leads 133 are protected with a resin layer 137.

[0023] The TCP 131 arranged as above includes the film base 134 to which an adhesive for forming the adhesive layer 135 is applied in advance, and through which a device hole 131a as a space for mounting the LSI chip 132 is formed. Then a conductive material such as a copper film is pasted on the film base 134, and wires including the leads 133 is formed by etching the conductive material. The TCP 131 arranged as above has an advantage so that the leads 133 can be easily aligned with the bumps 136, since the leads 133 are provided as jutting into the device hole 131a.

[0024] However, the above-arranged TCP 131 has a disadvantage so that it is impossible to provide any wires except the ones connected to the LSI chip 132 in the area where the LSI chip 132 is provided, due to the existence of the device hole 131a. A material used for the leads 133 (wire) is a conductive material such as a copper film sized around 20 μm thick and 40 μm wide, so as to be disconnected easily. Therefore even if one tries to mount the LSI chip 132 in the device hole 131a in which no film base is

provided by leaving only the wires, the wires are easily disconnected by stress generated in the process of mounting the LSI chip 132.

[0025] Moreover, stress is generated due to an injection of a resin material into the device hole 131a when the resin layer 137 is formed. So the wires not fixed on the film base 134 are pushed away owing to the stress so as to be short-circuited with other wires or the bumps 136 formed on the LSI chip 132. Incidentally, the thickness of the film base 134 is around 75 μm .

SUMMARY OF THE INVENTION

[0026] The present invention aims at providing:

[0027] a display element driving apparatus in which a set of wires, which is not connected to a drive LSI chip (integrated circuit), can be provided in the shortest distance without disconnecting the same; and

[0028] a display using the same, in which a plurality of drive LSI chips is mounted on a liquid crystal panel etc.

[0029] To achieve this aim, the display element driving apparatus of the present invention and a display element integrated circuit of the display using the apparatus includes:

[0030] first and second integrated circuits for driving a display element having a plurality of first electrodes and a plurality of second electrodes which cross each other in a matrix manner, the first integrated circuit including a chip into which a first drive circuit for driving the first electrodes, and the second integrated circuit including a chip into which a second drive circuit for driving the second electrodes; and

[0031] a single mounting substrate, including connecting terminals and connecting wires which connect the connecting wires which connect the connecting terminals and the first integrated circuit, for mounting the first and second integrated circuits such that the first integrated circuit is closer to the display element than the second integrated circuit between the connecting terminals and the display element,

[0032] wherein the connecting wires are fixed in the substrate so as to pass through an mounting area of the second integrated circuit.

[0033] According to this arrangement, the first integrated circuit is provided to be relatively close to the display element whereas the second integrated circuit is provided to be relatively far from the display element, between the connecting terminals and the display element on the single mounting substrate. Thus it is necessary to provide the first and second integrated circuits close to each other, if one tries to reduce the area of the mounting substrate.

[0034] In this type of arrangement the shortest path for the connecting wires to connect the connecting terminals to the first integrated circuit is blocked by the second integrated circuit. However, the connecting wires are provided to pass through the mounting area for the second integrated circuit so that the connecting wires do not have to avoid the mounting area. Thus it is possible to provide the connecting

wires in the shortest distance and hence the area of the mounting substrate can be reduced. Moreover, the connecting wires are fixed on the mounting substrate so that the wires are not disconnected on account of stress generated in a process of mounting the second integrated circuit on the mounting substrate. Therefore it is possible to cut the cost of the display element driving apparatus.

[0035] For a fuller understanding of the nature and advantages of the invention, reference should be made to the ensuing detailed description taken in conjunction with the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0036] FIG. 1 is a plan view showing a liquid crystal panel and an arrangement of a mounting package attached to the same in accordance with a liquid crystal module of an embodiment of the present invention.

[0037] FIG. 2 is a block diagram showing an arrangement of the liquid crystal module which is shared between all embodiments of the present invention.

[0038] FIG. 3(a) is a side view showing an arrangement of a mounting package, which is shared between all embodiments of the present invention, in which leads are provided below an LSI chip for driving a scanning line electrode, whereas FIG. 3(b) is a plan view showing the arrangement from a film base side.

[0039] FIG. 4 is a plan view showing an arrangement of bumps on the LSI chip.

[0040] FIG. 5 is a plan view showing another arrangement of bumps on the LSI chip.

[0041] FIG. 6 is a plan view showing an arrangement of wires connected to the LSI chip including protrusions.

[0042] FIG. 7 is a plan view showing an arrangement of the film base including protrusions.

[0043] FIG. 8 is a plan view showing an arrangement of wires connected to the LSI chip not including protrusions.

[0044] FIG. 9 is a plan view showing another arrangement of wires connected to the LSI chip not including protrusions.

[0045] FIG. 10 is a plan view showing another arrangement of wires connected to the LSI chip including protrusions.

[0046] FIG. 11(a) is a plan view showing an arrangement of wires connected to the LSI chip in which various circuits are provided, and FIG. 11(b) is a block diagram showing arrangements of the circuits.

[0047] FIG. 12 is a plan view showing a liquid crystal panel and an arrangement of a mounting package attached to the same in accordance with a liquid crystal module of another embodiment of the present invention.

[0048] FIG. 13 is a plan view showing an arrangement of a main part of a conventional matrix-type liquid crystal display panel.

[0049] FIG. 14 is a plan view showing an arrangement in which a drive LSI chip is mounted on a glass substrate of a liquid crystal panel by a TCP.

[0050] **FIG. 15** is a plan view showing an arrangement in which the drive LSI chip is directly mounted on the glass substrate of the liquid crystal panel by a COG technique.

[0051] **FIG. 16** is a plan view showing an arrangement in which more than one drive LSI chip are mounted on the glass substrate of the liquid crystal panel by the TCP.

[0052] **FIG. 17** is a plan view showing an arrangement in which the single drive LSI chip is mounted on the glass substrate of the liquid crystal panel by the TCP.

[0053] **FIG. 18** is a front view showing an arrangement in which a display area, whose left margin with respect to a liquid crystal panel arranged as shown in **FIG. 15** is not equal to the right margin thereof, is provided on the panel.

[0054] **FIG. 19** is a front view showing an arrangement in which the display area, whose left margin with respect to the liquid crystal panel arranged as shown in **FIG. 15** is equal to the right margin thereof, is provided on the panel.

[0055] **FIG. 20** is a side view showing how an LSI chip is mounted in a conventional TCP.

DESCRIPTION OF THE EMBODIMENTS

[0056] The following description will discuss an embodiment in accordance with the present invention in reference to FIGS. 1 to 11.

[0057] As **FIG. 2** shows, a liquid crystal module in accordance with the present invention includes a liquid crystal panel 1, surrounding circuits (described later) and so forth.

[0058] The liquid crystal panel 1 as a display element is a general STN liquid crystal panel, including a group 2 of scanning line electrodes, a group 3 of data line electrodes, and a liquid crystal (not illustrated) sandwiched between the groups 2 and 3 which are arranged in a matrix manner. The group 2 of scanning line electrodes is made up of scanning line electrodes X1 to Xn provided sideways and being, in parallel with each other. Meanwhile, the group 3 of data line electrodes is made up of data line electrodes Y1 to Yn provided longitudinally, crossing the scanning line electrodes Xi to Xn at right angles and being in parallel with each other. Moreover, a pixel P is formed at the intersection of the scanning electrode Xi (m=i) and the data line electrode Yj (n=j). The pixels P are provided within a display area 1a of the liquid crystal display 1 in a matrix manner.

[0059] A scanning line electrode driving circuit 11 (hereinafter, will be simply referred to as common driver) and a data line electrode driving circuit 12 (hereinafter, will be simply referred to as segment driver) are connected to the liquid crystal panel 1. Moreover, a control circuit 13 and a voltage generating circuit 14 are connected to the common driver 11 and the segment driver 12. A scanning signal for selecting which scanning line electrodes X1 to Xm are driven is transmitted from the common driver 11 to the group 2 of scanning line electrodes. In the meantime, a data signal in accordance with data for display is transmitted from the segment driver 12 to the group 3 of data line electrodes.

[0060] The control circuit 13 receives the data for display from a VRAM 15 storing the data for display, and provides a control signal CTL for controlling display to the drivers 11

and 12 in accordance with an external instruction transmitted via a system bus 16. The control signal provided to the segment driver 12 includes the data for display.

[0061] The voltage generating circuit 14 generates 6 different types of voltages V0 to V5 for display. The circuit 14 provides the voltages V0, V1, V4, and V5 to the common driver 11 and the voltages V0, V2, V3, and V5 to the segment driver 12. A signal level for driving a liquid crystal is determined in accordance with these voltages V0 to V5. The definition of a waveform of a voltage for driving is omitted since the same is described in the aforementioned Japanese Laid-Open Patent Application etc.

[0062] Moreover, a supply voltage Vcc, a reference voltage Vss, and a boosted supply voltage Vdd are provided to the drivers 11 and 12. The supply voltage Vcc is a voltage (5V system) for logic driving, whereas the reference voltage Vss is a standard voltage such as a ground electric potential. The boosted source voltage Vdd is a boosted voltage for driving an output stage, and some driving methods require the same (for instance 20V).

[0063] As **FIG. 1** shows, a mounting package 21 is connected to a side of a glass substrate 1 of the liquid crystal panel 1. The mounting package 21 is a package mounting:

[0064] an LSI chip 23 (second integrated circuit) into which the common driver 11 is integrated; and

[0065] an LSI chip 24 (first integrated circuit) into which the segment driver 12 is integrated,

[0066] on an insulating film base 22 made of polyimide etc. using a technique termed COF (Chip On Film). An edge of this mounting package 21 is connected to ITO (Indium Tin Oxide), which is for connecting, of the liquid crystal panel 1.

[0067] On the film base 22 as a mounting substrate, an LSI chip 24 is provided on the side near the liquid crystal panel 1 whereas an LSI chip 23 is provided on the side far from the liquid crystal panel 1. The film base 22 also includes:

[0068] two sets of wires 25 for connecting the LSI chip 23 to the liquid crystal panel 1; and

[0069] a set of wires 26 for connecting the LSI chip 24 to the liquid crystal panel 1.

[0070] The set of wires 26 is made up of conductive wires (copper wires) fixed on the film base 22. Meanwhile, the sets of wires 25 as output wiring, also made up of conductive wires (copper wires) fixed on the film base 22, are provided to pass by the both sides of the LSI chip 24. The film base 22 further includes a group 27 of connecting terminals provided on an edge opposite to the edge connected to the liquid crystal panel 1.

[0071] A set of wires 28 formed on the film base 22 connects the LSI chips 23 and 24 to the group 27 of connecting terminals, and this set of wires 28 is also made up of conductive wires (copper wires) fixed on the film base 22. The set of wires 28 contains a first set of wires 28a connected to the LSI chip 23 and a second set of wires 28b passing under the LSI chip 23 to be connected to the LSI chip 24, as connecting wires.

[0072] Incidentally, the second set of wires 28b may include not only wires for inputting the control signal CTL,

the voltages V0, V2, V3, and V5 (for the segment driver 12), the supply voltage Vcc, the reference voltage Vss, and the boosted supply voltage Vdd, but also a wire for outputting a signal. For instance, the signal may be a start pulse signal included in the control signal CTL and transmitted in a shift register provided in the segment driver 12. A pulse signal, transmitted from each output stage of the shift register is used as a sampling signal for selecting either one of the voltages V0, V2, V3, and V5 which is matched with display data provided for the data line electrodes Y1 to Yn, during the start pulse signal is transmitted in the shift register.

[0073] After transmitted in the shift register, the start pulse signal is again transmitted from the group 27 of connecting terminals via the second set of wires 28b, to an unillustrated external controller (may be the control circuit 13) etc. This controller either terminates the transmission of the data for display in one horizontal scanning period or resets a counter of a display data output processing circuit in the controller, when detecting the start pulse signal.

[0074] Similarly, the first set of wires 28a may include not only wires for inputting the control signal CTL, the voltages V0, V1, V4, and V5 (for the common driver 11), the supply voltage Vcc, the reference voltage Vss, and the boosted supply voltage Vdd, but also a wire for outputting a signal. For instance, the signal may be a start pulse signal included in the control signal CTL and transmitted in a shift register provided in the common driver 11.

[0075] After transmitted in the shift register, the start pulse signal is again transmitted from the group 27 of connecting terminals via the first set of wires 28a, to the controller etc. This controller either terminates the transmission of the data for display in one vertical scanning period or resets the counter of the display data output processing circuit in the controller, when detecting the start pulse signal.

[0076] The film base 22 may be made up of three layers in which a multiple number of films and conductive wires are adhered via an adhesive layer, or two layers in which the films and wires are adhered by thermocompression instead of using the adhesive. The film base 22 is, for instance, around 40 μm thick while the conductive wires are around 10 μm thick and 28 μm wide.

[0077] By the way, not only the film base 22 but also a ceramic board etc. can be used as the mounting substrate.

[0078] Although not illustrated, ITO wires on the liquid crystal panel 1 and the conductive wires on the film base 22 are electrically connected and thereby fixed by thermocompression via an ACF (Anisotropic Conductive Film).

[0079] The following description will discuss an arrangement in which the set of wires 28 passes under the LSI chip 23.

[0080] As shown in FIGS. 3(a) and 3(b), in the mounting package 21, LSI chip 23 is mounted on the film base 22. LSI chip 23 is connected to leads 31 via the bumps 23a that are connecting electrodes for an external electric connection. The leads 31 as conductive wires constitute the first set of wires 28a. The LSI chip 23 and the leads 31 are protected with a resin layer 34. In this arrangement, a mounting area for the LSI chip 23 is provided on the film base 22 and the bumps 23a are aligned with the leads 31. Also, the leads 31

and leads 32 to be described later are protected with a protector 35 made up of a solder resist etc.

[0081] FIG. 3(b) shows wires on the mounting package 21 from its side facing the film base 22 without illustrating the base 22. As the figure indicates, the leads 31 are connected to the bumps 23a in the same manner as in a conventional TCP (see FIG. 20). However, the film base 22 exists below the mounted LSI chip 23 in this case. On the mounting area for the LSI chip 23 on the base 22, the leads 32 which are not connected to the LSI chip 23 are fixed. Thus the leads 32 are neither disconnected when the LSI chip 23 is mounted nor pushed away by stress generated when the resin material is injected around the LSI chip 23.

[0082] Therefore, it is possible to provide the leads 32, which is not connected to the LSI chip 23, under the LSI chip 23 (between the film base 22 and the LSI chip 23), when the mounting structure above is adopted. On this account, even if in the mounting package 21 the LSI chips 23 and 24 are mounted on the single film base 22, the leads 32 constituting the second set of wires 28b do not have to take indirect paths along the both sides of the LSI chip 23 so that the signal wires can take a simple path. Furthermore, the size of the film base 22 can be reduced and hence the cost of manufacturing the mounting package 21 can be reduced.

[0083] Two sets of wires 25 between the LSI chip 23 and the liquid crystal panel 1 are provided along the both sides of the LSI chip 24 so that the sets of wires 25 are not provided between the LSI chips 23 and 24. On this account, the second set of wires 28b is connected to the LSI chip 24 by passing under the LSI chip 23, which is the shortest path. Moreover, the size of the film base 22 can be reduced by providing the two sets of wires 25 close to the LSI chip 24 as much as possible.

[0084] In the mounting package 21 arranged as above, a substrate (not illustrated) on which the control circuit 13, the voltage generating circuit 14, a VRAM 16, etc. are mounted is connected to the group 27 of connecting terminals of the film base 22. On this account, the control signal CTL for the LSI chip 23 transmitted from the control circuit 13 is input to the group 27 of connecting terminals, and then input to the LSI chip 23 via the first set of wires 28a. Meanwhile, the control signal CTL for the LSI chip 24 transmitted from the control circuit 13 is input into the group 27 of connecting terminals, and then input to the LSI chip 24 via the second set of wires 28b passing under the LSI chip 23.

[0085] Moreover, the LSI chips 23 and 24 are separately provided so that these LSIs can be manufactured in each different process. For instance, it is possible to manufacture the LSI 24 in a common manufacturing method with low cost. Thus it is possible to cut the production cost of the LSI chip 24 and consequently cut the cost of the liquid crystal module including the liquid crystal panel 1 as well as the mounting package 21.

[0086] FIG. 4 shows the LSI chip 23 including the bumps 23a which are connecting electrodes on the opposing edges of the chip. More specifically, the bumps 23a are provided along the edges of a mounting face 23e (bottom face) of the LSI chip 23 facing the film base 22, except around the middle parts of the longer sides of the face 23e. On this account, a large space (passing area) across which the second set of wires 28b can pass is provided in the middle

of the mounting face **23e** of the LSI chip **23**. Also, as shown in **FIG. 3(a)**, the LSI chip **23** is sealed with the resin layer **34** except the top face thereof and the areas for contacting with the bumps **23a**. On this account, the wires provided in the space below the LSI chip **23** do not short-circuit with other wires connected to the LSI chip **23**.

[0087] Incidentally, the height of the bump **23a** is around $10 \mu\text{m}$ so that the central part of the LSI chip **23**, on which the bumps **23a** are not formed, are hardly stressed when the LSI chip **23** is mounted, provided that the LSI chip **23** is not large in size. However, if the LSI chip **23** is large in size, the stress may be applied to the central part of the LSI chip **23** due to its long narrow shape. Moreover, when a resin is injected into the gap between the LSI chip **23** and the film base **22** to form the resin layer **34** after these two are connected, the resin may not be spread uniformly on the opposing edges of the LSI chip **23** since the bumps **23** are intensively provided thereon.

[0088] To resolve the problem above, for instance, protrusions **23b** which are more or less flush with the bumps **23a** are provided in the middle of the mounting face **23e** of the LSI chip **23**, as **FIG. 5** shows. The protrusions **23b** are provided along the middle parts of the longer sides of the LSI chip **23**. The protrusions **23b** are made of a non-conductive material and hence not to be short-circuited with the wires on the film base **22**.

[0089] Providing the protrusions **23b** makes it possible not only to spread the resin uniformly but also to reduce the stress generated in the LSI chip **23** when the same is mounted, thus it is possible to prevent warpage of the LSI chip **23** due to the stress. It has been pointed out that warpage of an LSI chip could change a characteristic thereof, and especially a change of a characteristic of an analog circuit is thought to be problematic. A thinner LSI chip suffers more damage from this, so taking a increase of a demand for a thinner LSI chip in the future into account, preventing warpage of the LSI chip as above is preferable.

[0090] Moreover, the resin layer **34**, formed by injecting and hardening the resin after the mounting of the LSI chip **23**, supports the middle part of the LSI chip **23** as a spacer on the film base **22**, and hence the LSI chip **23** does not suffer warpage under its own weight. In other words, the LSI chip **23** is fixed with the resin layer **34** in the condition when the chip is mounted.

[0091] By the way, it is preferable to arrange a pitch (arrangement intensity) of the protrusions **23b** substantially equal to that of the bumps **23a**, to spread the resin uniformly.

[0092] **FIG. 6** indicates an arrangement of wires connected to the LSI chip **23** including the protrusions **23b**. The set of wires **28** connected to the group **27** of connecting terminals includes a signal wire for the control signal CTL provided to the LSI chips **23** and **24** and power supply wires for inputting the aforementioned voltages. Among the wires, the first set of wires **28a** is connected to the connecting electrodes (bumps **23a**) of the LSI chip **23** whereas the second set of wires **28b** passes under the LSI chip **23** so as to be connected to the LSI chip **24**. The mounting face **23e** of the LSI chip **23** does not have any conductive connecting electrodes on the area where the second set of wires **28b** passes across so that the second set of wires **28b**, an internal circuit of the LSI chip **23** etc. are not short-circuited with each other since such connecting electrodes do not exist.

[0093] The protrusions **23b** are provided with distance from the wires connected to the LSI chip **24** so as not to make contact with the wires, when the LSI chip **23** is mounted on the film base **22**. Moreover, the protrusions **23b** are made of a non-conductive material so that the protrusions **23b** are not short-circuited, etc. even if the same make contact with the wires.

[0094] By the way, although the protrusions **23b** are provided on the LSI chip **23** in advance here, the same may be provided on the film base **22** in advance.

[0095] For instance, as **FIG. 7** shows, protrusions **22a** are provided on a mounting area **22b** of the film base **22** on which area the LSI chip **23** is mounted. The protrusions **22a** are provided along the middle part of the longer side of the mounting area **22b**. When the LSI chip **23** is mounted, the film base **22** is fixed on a flat supporting base so that the protrusions **22a** suppress the stress generated in the LSI chip **23**. Thus the warpage of the LSI chip **23** can be prevented as in the arrangement in which the protrusions **23b** are provided on the LSI chip **23**.

[0096] The two sets of wires **25** surround the opposing sides of the LSI chip **23** so as to be connected to the same in advance, as shown in **FIG. 6**. On this account, the sets of wires **25** are provided along the edges of the opposing sides of the film base **22** as shown in **FIG. 1**, and connected to scanning line electrode input terminals which face each other on the liquid crystal panel **1**, as described above.

[0097] An arrangement of wires to the LSI chip **24** is identical with the conventional arrangement and thus omitted.

[0098] The layout of the bumps **23a** on the LSI chip **23** and the wiring pattern on the film base **22** are not particularly limited to the arrangement shown in **FIG. 6** so that the bumps **23a** and the wiring pattern may be, for instance, arranged as shown in **FIGS. 8 to 11**.

[0099] In the arrangement shown in **FIG. 8**, the bumps **23a** to which the first set of wires **28a** to be input wires for the LSI chip **23** are connected are all provided along the edge of the middle part of the input side of the LSI chip **23**. In the meantime, two sets of the second set of wires **28b** are provided on the both sides of the first set of wires **28a**, but on the middle part of the LSI chip **23** on which the first set of wires **28a** is not provided, the two sets of the second set of wires **28b** are joined together.

[0100] On this account, unlike the arrangement in which the two sets of the first set of wires **28a** are provided on the both sides of the second set of wires **28b**, the first set of wires **28a** is all provided on the middle part of the LSI chip **23** in this arrangement. Moreover, the protrusions **23b** included in the LSI chip **23** shown in **FIG. 6** are unnecessary in this arrangement, since the bumps **23a** are provided on the middle part of the LSI chip **23**.

[0101] Although the wires in **FIG. 6** are illustrated linearly, as described above, the power supply wires (Vcc, Vss, Vdd, and V0 to V5) etc. provided commonly in the LSI chips **23** and **24** have branches to be connected to the LSI chips **23** and **24** (see **FIG. 10**).

[0102] In an arrangement shown in **FIG. 9**, the bumps **23a** for connecting the first set of wires **28a**, which is input/output wire of the LSI chip **23**, are provided not along the

edges of the longer sides of the LSI chip **23** as in the arrangement in **FIG. 6** but in the middle of the LSI chip **23**, more specifically between the rows of the bumps provided along the edges of the longer sides of the LSI chip **23**. In this arrangement it is possible to reduce lengths of the longer sides of the LSI chip **23** so as to reduce the area of the LSI chip **23**.

[0103] The protrusions **23b** may be provided on the LSI chip **23** of this arrangement too.

[0104] In an arrangement shown in **FIG. 10**, common wires for both of the LSI chips **23** and **24** can be connected to the LSI chip **23**. More specifically, the LSI chip **23** includes bumps **23c** on the mounting face **23e**, which are connected to wires branched off from particular wires (such as a power supply wire) among the second set of wires **28b**. The bumps **23c** are provided along with the bumps **23a** to which the first set of wires **28a** are connected, and at the same time the bumps **23c** are provided to be far from the second set of wires **28b** to avoid short-circuit. The bumps **23c** may be provided where the second set of wires **28b** passes through. If the bumps **23c** are provided in this area, it is unnecessary to make the wires branch off from the second set of wires **28b** as above.

[0105] An arrangement shown in **FIG. 11(a)** is preferably used for the mounting package **21** in which circuits such as a buffer, an amplifier, and a level shifter are provided for interpolation, amplification, impedance conversion, and level shift, etc. of a signal which is damped during transmission from other LSIs. Other unillustrated LSIs including the LSI chip **24** may include similar circuits and have a similar arrangement of bumps to be discussed later.

[0106] In this arrangement, the LSI chip **23** includes bumps **23d₁** to **23d₄** and bumps **23d₁₁** to **23d₁₄** for connecting the second set of wires **28b**. Moreover, as **FIG. 11(b)** shows, internal circuits **41** to **44**, which are processing circuits including a buffer, an amplifier, and a level shifter, etc. for variously processing an input signal transmitted to the LSI chip **24**, are provided in the LSI chip **23**. Input terminals of the internal circuits **41** to **44** are respectively connected to the bumps **23d₁** to **23d₄**, whereas output terminals thereof are respectively connected to the bumps **23d₁₁** to **23d₁₄**.

[0107] It is unnecessary to independently provide a circuit on the film base **22**, which signal is for treating a signal transmitted in the second set of wires **28b**, so that the area of the mounting package **21** can be further reduced.

[0108] Incidentally, although each of the internal circuits **41** to **44** individually gives a predetermined of treatment to four signals in the arrangement above, as long as at least one signal is treated, the numbers of signals to be treated are not particularly limited.

[0109] As a concrete example of the liquid crystal panel **1**, a panel also including 128 (data side)×3 (R, G, and B)×164 (scanning side) pixels as in the panel in Background of the Invention is described below.

[0110] The LSI chip **24** includes 384 (=128×3) terminals as output terminals, and transmits a driving signal to the liquid crystal panel **1** via the set of wires **26**. The main control signals CTL to be transmitted to the LSI chip **24** are such as a data transmission clock signal, a start pulse signal,

a latch signal, data for display, an AC conversion signal, and a brightness control signal, etc.

[0111] The data transmission clock signal is a clock signal for transmitting sets of the data for display to according R, G, and B in the shift register inside the LSI chip **24**. The start pulse signal controls the start of the transmission. The latch signal latches a signal acquired as a result of the transmission of the data for display in one horizontal synchronizing period. The AC conversion signal converts the data signal transmitted from the LSI chip **24**, which is for driving a liquid crystal with AC, into AC. The brightness control signal controls a voltage level of the data signal, to adjust the brightness of the display.

[0112] Moreover, as described above, the supply voltage Vcc, the reference voltage Vss, the boosted supply voltage Vdd, and the voltages V0, V2, V3, and V5 (see **FIG. 2**) to be applied to the liquid crystal panel **1** are provided for the LSI chip **24**.

[0113] Generally an LSI chip for driving a data line electrode such as the LSI chip **24** has a very narrow rectangular shape since the chip has a lot of outputs and a few inputs. Thus in the LSI chip the output terminals are provided along the longer side of the chip which side is close to the liquid crystal panel **1**, the shorter sides, and a part of the other longer side, whereas terminals for an input signal and power supply are provided along the other longer side.

[0114] In the meantime, main control signals transmitted to the LSI chip **23** are such as a transmission signal, a start pulse signal, and an AC conversion signal, etc. The transmission signal is a signal (such as a horizontal synchronizing signal) that transmits a scanning signal in the shift register inside the LSI chip **23**. The start pulse signal controls the start of the transmission. The AC conversion signal converts the scanning signal, which is for driving a liquid crystal with AC, into AC.

[0115] Moreover, as described above, the supply voltage Vcc, the reference voltage Vss, the boosted supply voltage Vdd, and the voltages V0, V1, V4, and V5 (see **FIG. 2**) to be applied to the liquid crystal panel **1** are provided for the LSI chip **23**.

[0116] Generally an LSI chip for driving a scanning line electrode such as the LSI chip **23** also has a lot of outputs and a few inputs as in the case of the LSI chip for driving the data line electrode so that the chip has a very narrow rectangular shape. Thus in the LSI chip the output terminals are provided along the longer side of the chip which side is close to the liquid crystal panel **1**, the shorter sides, and a part of the other longer side, whereas terminals for input and output signals and power supply are provided along the other longer side.

[0117] In many cases the liquid crystal panel **1** has a lot of pixels aligned sideward (longitudinal direction of the scanning line electrode Y) and therein sets of the display data of each of R, G, and B are dealt with individually. On this account, the output terminals included in the LSI chip for driving the scanning line electrode are fewer than those in the LSI chip for driving the data line electrode.

[0118] Therefore, in the present embodiment it is possible to provide the two sets of wires **25** on the both right and left sides of the liquid crystal panel **1** with ease by providing the

signal wire and power supply wire (the numbers of these wires may be relatively few), that are connected to the LSI chip **24**, under the LSI chip **23**. On this account, it is possible to implement the arrangement of wires allowing to be arranged the display area **1a** in the middle of the liquid crystal panel **1** with ease. Moreover, two LSI chips **23** and **24** having narrow rectangular shape can be mounted side by side with the longer sides thereof confronting each other since the wires do not obstruct to implement this arrangement, and hence it is possible to mount LSI chips highly densely. Furthermore, related LSI chips (including related LSIs such as the control circuit **13**) can be mounted on the film base **22** so that it is possible to further reduce the size of the liquid crystal module.

[0119] As described above, it is possible to simplify the routing of input signal wires by providing the second set of wires **28b** passing under the LSI chip **23** (mounting area **22b**), even if the LSI chips **23** and **24** are mounted on the single film base **22**. Thus it is unnecessary to provide more than one LSI chip **23**.

[0120] Moreover, it is possible to shorten the lengths of a high-speed data transmission clock wire and a high-speed data wire so that it is possible to prevent degradation of the quality of the display due to external noise, and also it becomes easy to design the arrangement of the display module. Also the power supply wire can be routed in a short distance. On this account, it is possible to prevent degradation of the quality of the display due to noise entering into the power supply wire.

[0121] As described above, it becomes easy to design the arrangement of wires connected to the film base **22** due to the simplified routing of the wires. Coupled with the high density mounting of the LSI chips **23** and **24**, this reduces the area of the film base **22** and cuts the cost of the mounting package **21**.

[0122] Furthermore, the simplification of the routing of the wires makes it possible to provide the wires in a single layer or on the both sides of the chip so that the film base **22** no longer requires more than one layer. On this account, it is possible to design the display module with ease and the same can be manufactured in a smaller size, since the film base **22** is thin enough so as to have flexibility. This arrangement is especially useful for mobile devices such as a mobile phone that particularly requires down-sizing, weight-reduction and cost-cutting.

[0123] The arrangement of wires between the LSI chips **23** and **24** becomes simple so that mounting and wiring the components other than the driving device become easy too. Particularly, passing wires are all arranged on the wiring area so that it is unnecessary to connect terminal electrodes of the LSI chip **23** to that of the LSI chip **24** and the input wires can be provided separately from the output wires. Thus the wires can be routed in the shortest distance and the wiring can be arranged easily, and it is possible to provide the display panel **1** in which peripheral devices are mounted on the single film base **22**, so that the manufacturing process of the display module can be dramatically simplified and reliability thereof is improved.

[0124] The following description will discuss another embodiment in accordance with the present invention in reference to FIGS. 2, 3, and 6 to 12. By the way, members

having the same functions as those described in the embodiment shown in FIG. 1 are given the same numbers, so that the descriptions are omitted for the sake of convenience.

[0125] A liquid crystal module in accordance with the present embodiment includes, as FIG. 2 shows, a liquid crystal panel **1**, a common driver **11**, a segment driver **12**, a control circuit **13**, a voltage generating circuit **14**, a VRAM **15**, etc., as in the liquid crystal module shown in FIG. 1. However, the liquid crystal panel **1** for the present liquid crystal module is connected not to the mounting package **21** shown in FIG. 1 but to a mounting package **51** shown in FIG. 12.

[0126] As in the case of the mounting package **21**, the mounting package **51** also includes a film base **22** on which LSI chips **23** and **24** are mounted, sets of wires **25**, **26**, and **28**, and a group **27** of connecting terminals. Moreover, a control chip **52** into which the control circuit **13**, the voltage generating circuit **14**, and the VRAM **15** are integrated, a voltage source chip **53**, and a VRAM chip **54** are further mounted on the film base **22** of the mounting package **51**.

[0127] A system bus **16** formed on the film base **22** connects the control chip **52** to the group **27** of connecting terminals. The set of wires **28** includes a voltage wire **28c** connected to the voltage source chip **53** and a power supply wire **28d** connected to the group **27** of connecting terminals. The voltage wire **28c** is provided to apply the aforementioned voltages **V0** to **V5** generated in the voltage source chip **53** to the LSI chips **23** and **24**. The power supply wire **28d** is provided to apply the supply voltage **Vcc**, the reference voltage **Vss**, and the boosted supply voltage **Vdd** supplied from the outside to the LSI chips **23** and **24**.

[0128] In the mounting package **51** arranged as above, a second set of wires **28b** on the film base **22** is also provided to pass under the LSI chip **23** using a COF technique shown in FIGS. 3(a) and (b), as in the mounting package **21** shown in FIG. 1. On this account, it is possible to prevent each wire included in the set of wires **28b** disconnected, as in the mounting package **21**.

[0129] Needless to say, in this embodiment, the connection between the LSI chip **23** and the set of wires **28** is arranged as shown in FIGS. 6 to 11 as in the embodiment shown in FIG. 1.

[0130] Although the example of the arrangement of electrodes on the liquid crystal panel **1** described in the present embodiment and the embodiment shown in FIG. 1 is a simple matrix type, the electrodes on the liquid crystal panel **1** may be differently arranged. For instance, when the liquid crystal panel **1** is TFT type, the common driver **11** and the segment driver **12** in FIG. 2 are respectively replaced by a gate driver and a source driver, and hence the LSI chips **23** and **24** mounted on the mounting package **21** or **51** are also respectively replaced by an LSI chip into which the gate driver is integrated and an LSI chip into which the source driver is integrated.

[0131] Moreover, although the example of the arrangement of the bumps **23a** allowing the second set of wires **28b** to pass across the LSI chip **23** is described in these two embodiments, the arrangement is not particularly limited to this example. Thus, for instance, there may be other ways to arrange the bumps to secure the wiring space on an LSI by developing alternative arrangements of the chips and wires on the film base **22**.

[0132] In a liquid crystal module adopting a panel structure in which two groups 3 of data line electrodes are provided respectively above and below the liquid crystal panel 1, the mounting packages 21 or 51 may be provided respectively upper and lower sides of the liquid crystal panel 1, when the liquid crystal panel 1 is a STN liquid crystal panel. Moreover, the LSI chip 24 may be made up of cascaded LSI chips.

[0133] Although those two embodiments describe the example in which the liquid crystal panel 1 is used as the display panel, the aforementioned arrangement can be applied to any kind of display panel as long as the same is driven by a drive LSI chip similar to that of the LSI chips 23 and 24.

[0134] Furthermore, those two embodiments can effectively be used in a multi-terminal display module in which the display panel 1 on which electrodes are provided in a matrix manner is driven by an X-axis driver (common driver) and a Y-axis driver (segment driver) and these drivers are mounted on an insulating film base including wires.

[0135] The display element driving apparatus is preferably arranged so that the mounting substrate includes output wires connecting the second integrated circuit to the display element, the output wires are provided so as to pass by both sides of the first integrated circuit from both ends of the second integrated circuit, and the connecting wires are provided to pass an area between the both ends of the second integrated circuit. In this arrangement the output wires from the second integrated circuit to the display element is provided to pass by the both sides of the first integrated circuit from the both ends of the second integrated circuit, and hence no output wire is provided between the second integrated circuit and the first integrated circuit. Thus it is possible to provide the connecting wires in the area where no output wire is provided, by providing the connecting wires to pass between the both sides of the second integrated circuit. On this account, it is possible to provide the connecting wires and the output wires in the shortest distances and further reduce the cost of the display element driving apparatus.

[0136] The display element driving apparatus is preferably arranged so that the second integrated circuit includes connecting electrodes provided in an area of a mounting face for the second integrated circuit other than areas where the connecting wires pass through, for electrically connecting to outside. There is no connecting electrode on the passing area for the connecting wires in this arrangement so that the connecting wires, passing across the mounting area for the second integrated circuit, do not contact the connecting electrodes. Thus it is possible to enhance reliability of the display element driving apparatus by eliminating unnecessary short-circuit.

[0137] Moreover, in the arrangement above it is preferable that the second integrated circuit includes non-conductive protrusions, provided on the passing area of the connecting wires, which are substantially flush with the connecting electrodes. Alternatively, in the arrangement above it is preferable that the mounting substrate includes non-conductive protrusions, provided on the passing area of the connecting wires, which are substantially flush with the connecting electrodes. In these arrangements it is possible to

eliminate local concentration of stress in the mounting substrate and thus the quality of the display element driving apparatus is improved.

[0138] The larger the second integrated circuit is, the more a part of the second integrated circuit in which the connecting electrode is not provided is vulnerable to an influence of stress, since the circuit is often formed to be a narrow rectangular shape because of the arrangement of the connecting electrodes thereon. So the local concentration of the stress can be eliminated by providing non-conductive protrusions, which are substantially flush with the connecting electrodes, on the passing area for the set of connecting wires.

[0139] It is preferable that each of the aforementioned display element driving apparatuses is arranged so that the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires. It is unnecessary to provide the processing circuit independently on the mounting substrate in this arrangement, and thus it is possible to further reduce the cost of the display element driving apparatus.

[0140] The display includes the display element and any one of the aforementioned display element driving apparatuses so that it is possible to acquire the display having the advantage of any one of the display element driving apparatuses.

[0141] The invention being thus described, it will be obvious that the same may be varied in many ways. Such variations are not to be regarded as a departure from the spirit and scope of the invention, and all such modifications as would be obvious to one skilled in the art intended to be included within the scope of the following claims.

What is claimed is:

1. A display element driving apparatus, comprising:

first and second integrated circuits for driving a display element having a plurality of first electrodes and a plurality of second electrodes which cross each other in a matrix manner, the first integrated circuit including a chip into which a first drive circuit for driving the first electrodes, and the second integrated circuit including a chip into which a second drive circuit for driving the second electrodes; and

a single mounting substrate, including connecting terminals and connecting wires which connect the connecting wires which connect the connecting terminals and the first integrated circuit, for mounting the first and second integrated circuits such that the first integrated circuit is closer to the display element than the second integrated circuit between the connecting terminals and the display element,

wherein the connecting wires are fixed in the substrate so as to pass through an mounting area of the second integrated circuit.

2. The display element driving apparatus as set forth in claim 1, wherein the mounting substrate includes output wires connecting the second integrated circuit to the display element, the output wires are provided so as to pass by both sides of the first integrated circuit from both ends of the

second integrated circuit, and the connecting wires are provided to pass an area between the both ends of the second integrated circuit.

3. The display element driving apparatus as set forth in claim 1, wherein the second integrated circuit includes connecting electrodes provided in an area of a mounting face for the second integrated circuit other than areas where the connecting wires pass through, for electrically connecting to outside.

4. The display element driving apparatus as set forth in claim 3, wherein the connecting electrodes are provided on the both sides of the second integrated circuit.

5. The display element driving apparatus as set forth in claim 2, wherein the second integrated circuit includes connecting electrodes provided in an area of a mounting face for the second integrated circuit other than areas where the connecting wires pass through, for electrically connecting to outside.

6. The display element driving apparatus as set forth in claim 5, wherein the connecting electrodes are provided on the both sides of the second integrated circuit.

7. The display element driving apparatus as set forth in claim 3, wherein the second integrated circuit includes non-conductive protrusions, provided on the passing area of the connecting wires, which are substantially flush with the connecting electrodes.

8. The display element driving apparatus as set forth in claim 3, wherein the mounting substrate includes non-conductive protrusions, provided on the passing area of the connecting wires, which are substantially flush with the connecting electrodes.

9. The display element driving apparatus as set forth in claim 1, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

10. The display element driving apparatus as set forth in claim 2, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

11. The display element driving apparatus as set forth in claim 3, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

12. The display element driving apparatus as set forth in claim 5, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

13. The display element driving apparatus as set forth in claim 7, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

14. The display element driving apparatus as set forth in claim 8, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

15. The display element driving apparatus as set forth in claim 1, wherein the first electrode is a data line electrode via which a data signal is transmitted, and the second electrode

is a scanning line electrode via which a scanning signal for selecting the second electrode is transmitted.

16. A display, comprising;

a display element including a plurality of first electrodes and a plurality of second electrodes crossing each other in a matrix manner; and

a display element driving apparatus including:

first and second integrated circuits for driving the display element having a plurality of first electrodes and a plurality of second electrodes which cross each other in a matrix manner, the first integrated circuit including a chip into which a first drive circuit for driving the first electrodes, and the second integrated circuit including a chip into which a second drive circuit for driving the second electrodes; and

a single mounting substrate, including connecting terminals and connecting wires which connect the connecting wires which connect the connecting terminals and the first integrated circuit, for mounting the first and second integrated circuits such that the first integrated circuit is closer to the display element than the second integrated circuit between the connecting terminals and the display element,

wherein the connecting wires are fixed in the substrate so as to pass through an mounting area of the second integrated circuit.

17. The display as set forth in claim 16, wherein:

the mounting substrate includes output wires connecting the second integrated circuit to the display element;

the output wires are provided to pass by both sides of the first integrated circuit from both ends of the second integrated circuit; and

the connecting wires are provided to pass an area between the both sides of the second integrated circuit.

18. The display as set forth in claim 16, wherein the second integrated circuit includes connecting electrodes provided in an area of a mounting face for the second integrated circuit other than areas where the connecting wires pass through, for electrically connecting to outside.

19. The display as set forth in claim 18, wherein the connecting electrodes are provided on the both ends of the second integrated circuit.

20. The display as set forth in claim 17, wherein the second integrated circuit includes connecting electrodes provided in an area of a mounting face for the second integrated circuit other than areas where the connecting wires pass through, for electrically connecting to outside.

21. The display as set forth in claim 20, wherein the connecting electrodes are provided on the both ends of the second integrated circuit.

22. The display as set forth in claim 18, wherein the second integrated circuit includes non-conductive protrusions, provided on the passing area of the connecting wires, which are substantially flush with the connecting electrodes.

23. The display as set forth in claim 18, wherein the mounting substrate includes non-conductive protrusions, provided on the passing area of the connecting wires, which are substantially flush with the connecting electrodes.

24. The display as set forth in claim 16, wherein the second integrated circuit includes a processing circuit for

giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

25. The display as set forth in claim 17, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

26. The display as set forth in claim 18, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

27. The display as set forth in claim 20, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

28. The display as set forth in claim 22, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

29. The display as set forth in claim 23, wherein the second integrated circuit includes a processing circuit for giving a predetermined of treatment to at least one signal among signals passing through the connecting wires.

30. The display as set forth in claim 16, wherein the first electrode is a data line electrode via which a data signal is transmitted, and the second electrode is a scanning line electrode via which a scanning signal for selecting the second electrode is transmitted.

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摘要(译)

液晶面板包括多个数据线电极和多个扫描线电极，它们彼此交叉并形成在这两者的交叉处以矩阵排列的像素。安装封装连接到液晶面板的玻璃基板的侧面的边缘。在安装封装的绝缘膜基底上，安装有用于驱动数据线电极的LSI芯片和用于驱动扫描线电极的LSI芯片。与后者相比，前LSI芯片设置为靠近液晶面板。将一组连接端子连接到LSI芯片的一组导线固定在薄膜基底上，以便通过薄膜基底上的LSI芯片(安装区域)下面。因此，在多个驱动LSI芯片安装在液晶上的布置中，可以在不断开连接的情况下以最短距离提供一组未连接到驱动LSI芯片的导线。小组等

